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Powering a Smarter World



September 16, 2026

Cautionary Note Regarding Forward-Looking Statements

This communication relates to a proposed business combination transaction between Synaptics Incorporated ("Synaptics") and ON Semiconductor Corporation ("onsemi"). This communication includes forward-looking statements within the meaning of Section 27A of the Securities Act of 1933, as amended, and Section 21E of the Securities Exchange Act of 1934, as amended. All statements, other than statements of historical facts, included or incorporated in this communication could be deemed forward-looking statements, particularly statements about future financial performance and forward-looking financial guidance. These forward-looking statements are based on Synaptics' and onsemi's current expectations, estimates and projections about the expected date of closing of the proposed transaction and the potential benefits thereof, their respective businesses and industries, management's beliefs and certain assumptions made by Synaptics and onsemi, all of which are subject to change. Some of these forward-looking statements can be identified by the use of forward-looking words such as "believes," "expects," "may," "will," "should," "seeks," "approximately," "intends," "plans," "estimates," "projects," "strategy," "anticipates," or "Target," or the negative of those words; other comparable terminology that convey uncertainty of future events or outcomes; or by discussions of strategy, plans, projections or intentions.

These forward-looking statements involve known and unknown risks and uncertainties, which may cause Synaptics' or onsemi's actual results and performance to be materially different from those expressed or implied in the forward-looking statements. Factors and risks that may impact future results and performance include, but are not limited to, the following factors: (1) the risk that the conditions to the closing of the transaction are not satisfied, including the risk that required approvals from regulators or the stockholders of Synaptics for the transaction are not obtained; (2) litigation relating to the transaction; (3) uncertainties as to the timing of the consummation of the transaction and the ability of each party to consummate the transaction; (4) risks that the proposed transaction disrupts the current plans and operations of Synaptics or onsemi, including restrictions during the pendency of the transaction that may impact the ability to pursue certain business opportunities or strategic transactions; (5) the ability of Synaptics and onsemi to retain and hire key personnel; (6) competitive responses to the proposed transaction; (7) unexpected costs, charges or expenses resulting from the transaction; (8) potential adverse reactions or changes to business relationships resulting from the announcement or completion of the transaction; (9) the combined companies' ability to achieve the growth prospects and synergies expected from the transaction, as well as delays, challenges and expenses associated with integrating the combined companies' existing businesses; (10) uncertainty as to the long-term value of onsemi's common stock; (11) legislative, regulatory and economic developments; and (12) unpredictability and severity of catastrophic events, including, but not limited to, acts of terrorism or outbreak of war or hostilities, as well as Synaptics' and onsemi's response to any of the aforementioned factors. These risks, as well as other risks associated with the proposed transaction, are more fully discussed in the proxy statement/prospectus that is included in the Registration Statement on Form S-4 that has been filed with the Securities and Exchange Commission ("SEC") in connection with the proposed transaction. While the list of factors presented here is considered representative, no such list should be considered to be a complete statement of all potential risks and uncertainties. Unlisted factors may present significant additional obstacles to the realization of forward-looking statements.

In addition, actual results are subject to other risks and uncertainties that relate more broadly to Synaptics' overall business, including those more fully described in Synaptics' filings with the SEC including its annual report on Form 10-K for the fiscal year ended June 27, 2026, and its quarterly reports filed on Form 10-Q for the current fiscal year, and onsemi's overall business and financial condition, including those more fully described in onsemi's filings with the SEC including its annual report on Form 10-K for the fiscal year ended December 31, 2025, and its quarterly reports filed on Form 10-Q for its current fiscal year.

Investing in onsemi's or Synaptics' securities involves a high degree of risk and uncertainty, and readers should carefully consider the trends, risks, and uncertainties described in this communication and other SEC filings of onsemi and Synaptics (including those referenced above) before making any investment decision. If any of these trends, risks, or uncertainties actually occurs or continues, the business, financial condition, or operating results of either or both companies could be materially adversely affected, the trading prices of each company's securities could decline, and investors could lose all or part of their investment. Forward-looking statements are not guarantees of performance, and speak only as of the date made, and neither onsemi, nor Synaptics nor the management of either entity undertakes any obligation to update or revise any forward-looking statements, except as may be required by law. All forward-looking statements attributable to onsemi, Synaptics, or persons acting on behalf of either company are expressly qualified in their entirety by this cautionary statement.

This is not an offer or solicitation. For additional information, please reference slides 99 – 100.

Use of Non-GAAP Financial Measures

This presentation contains historical non-GAAP financial measures including, among others, free cash flow (FCF) and FCF margin, non-GAAP gross margin and non-GAAP operating margin. This presentation also contains forward looking non-GAAP financial measures, some of which are adjusted for certain special items. These special items are out of our control and could change significantly from period to period. As a result, we are not able to reasonably estimate and separately present the individual impact of these special items, and we are similarly unable to provide a reconciliation of the non-GAAP measures. The reconciliation that is unavailable would include a forward-looking income statement, balance sheet, and statement of cash flows prepared in accordance with GAAP. We believe these non-GAAP measures provide important supplemental information to investors. We use these measures, together with GAAP measures, for internal managerial purposes and as a means to evaluate period-to-period comparisons. However, we do not, and you should not, rely on non-GAAP financial measures alone as measures of our performance. In addition, because non-GAAP financial measures are not standardized, it may not be possible to compare these financial measures with other companies' non-GAAP financial measures, even if they have similar names.

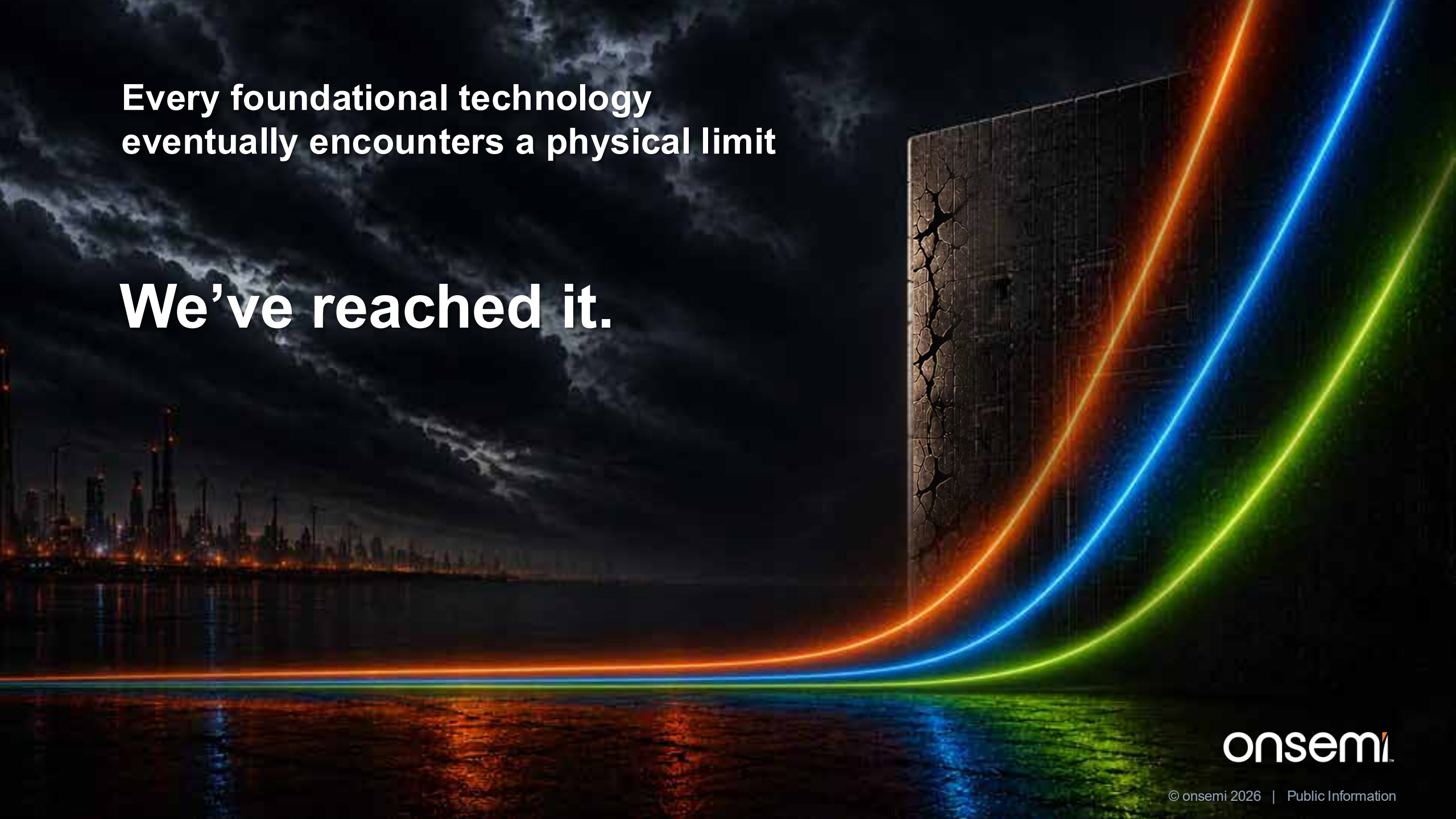
For a reconciliation of historical non-GAAP financial measures to GAAP, please see the Appendix on slide 89.

Powering a Smarter World

TOPIC	PRESENTER
Charting a Path to Power the Next Decade of Innovation	**Hassane El-Khoury** President & CEO
Powering the AI Revolution	**Achyut Shah** Group President, Power Solutions Group
Expanding the Core: Automotive and Industrial	**Sudhir Gopalswamy** Group President, Analog & Mixed-Signal and Intelligent Sensing Groups
Turning Technology Leadership into Durable Financial Performance	**Thad Trent** Executive Vice President & CFO
Q&A	**All**

Charting a Path to Power the Next Decade of Innovation

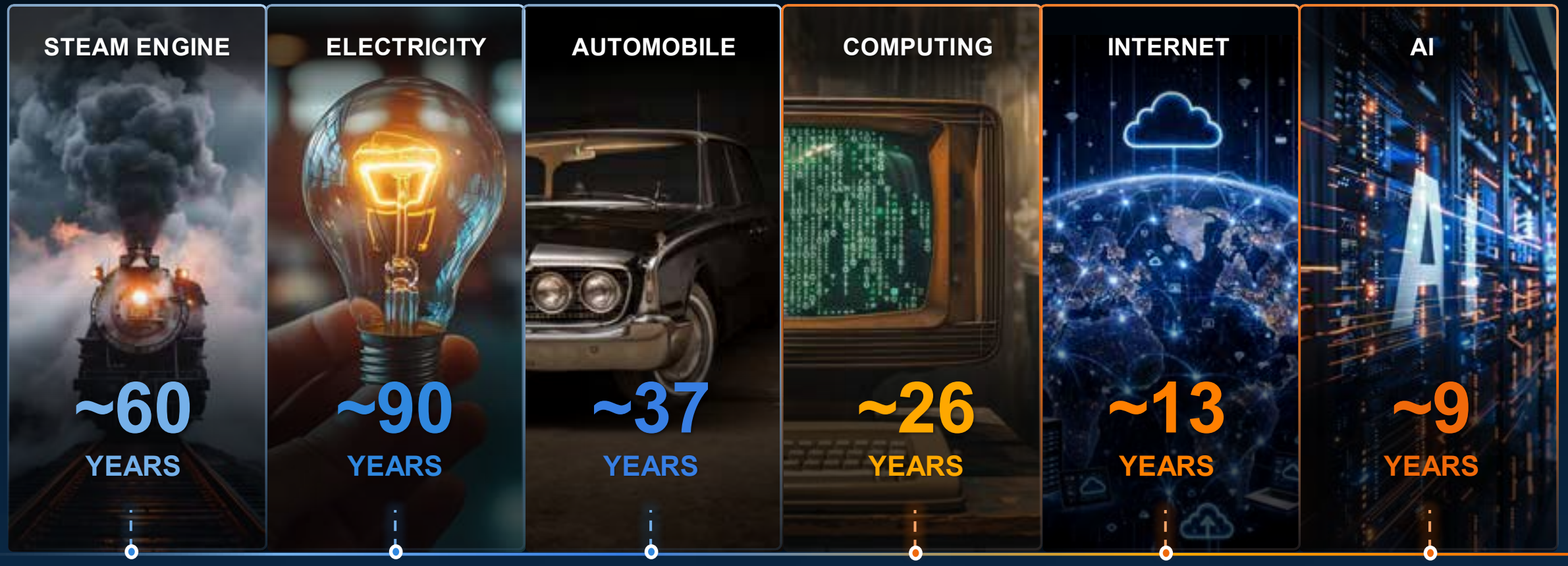
Hassane El-Khoury
President and CEO



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The Future is Arriving Faster Than Ever

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Precision metalworking	Grid & factory reorganization	Petroleum refining, fuel distribution & road network	Switching element – the transistor	Bandwidth & local access infrastructure	COMPUTE, MEMORY & POWER

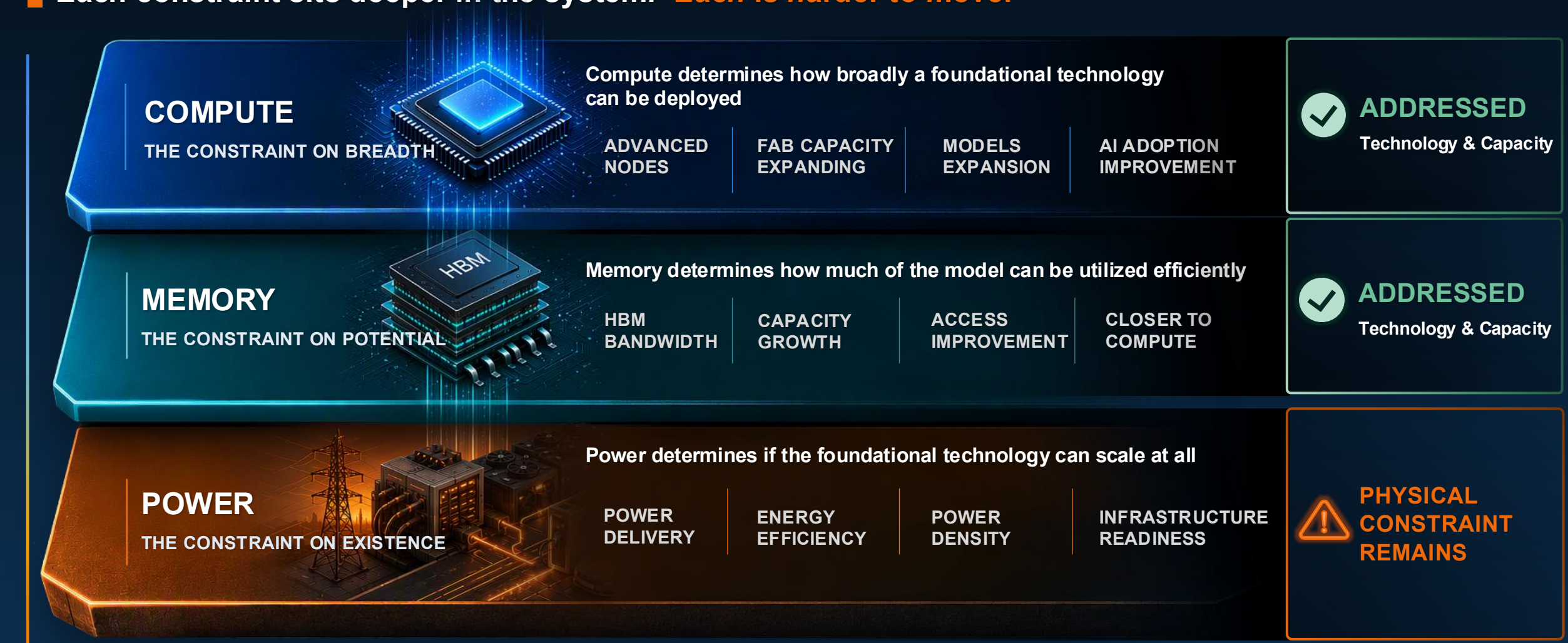
Every Foundational Technology Was Gated By A Physical Constraint

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Physical Constraint Ladder

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Each constraint sits deeper in the system. Each is harder to move.



MORE PHYSICAL

Until power density breaks through, the AI revolution is limited

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More Power Isn't Enough.
The World Needs Better Power.

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YESTERDAY: POWER SUPPORTED WORK

Factories	Predictable operations
Appliances	Intermittent usage
Buildings	Managed consumption
Conventional Vehicles	Mechanical systems

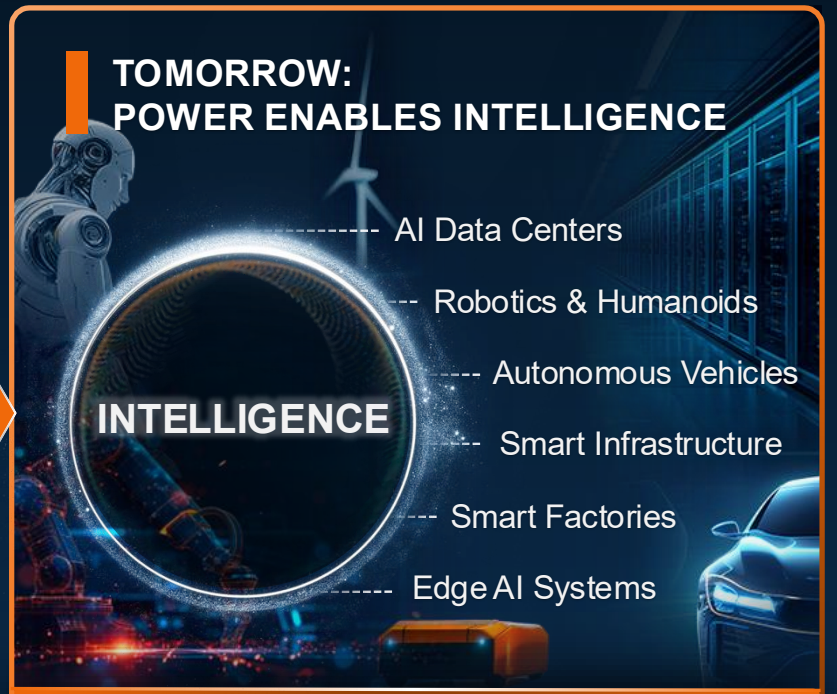
Power was relatively predictable and tolerant of inefficiency

THE CHALLENGE HAS CHANGED

POWER MUST BE

- More Efficient
- More Dense
- More Reliable
- More Precise
- More Autonomous
- More Scalable

TOMORROW: POWER ENABLES INTELLIGENCE



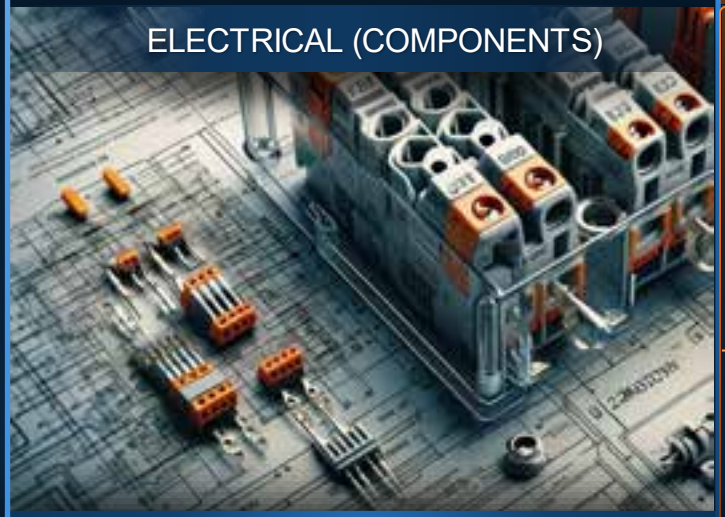
Power is always on, always connected, always at peak, and critical to performance

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WE SOLVED THE POWER OF YESTERDAY

ELECTRICAL (COMPONENTS)



More watts → Bigger → Centralized

Electrical	Thermal	Mechanical	Physical
Convert, control and distribute power efficiently	Move heat before it limits performance	Withstand stress and enable reliability	Design within the limits of physics

POWER OF TODAY

MULTI-PHYSICS SYSTEMS



More watts → Smaller → Distributed

MORE POWER. LESS SPACE. HIGHER EFFICIENCY. UNMATCHED RELIABILITY.

WE SOLVED POWER → **NOW WE SOLVE POWER DENSITY**

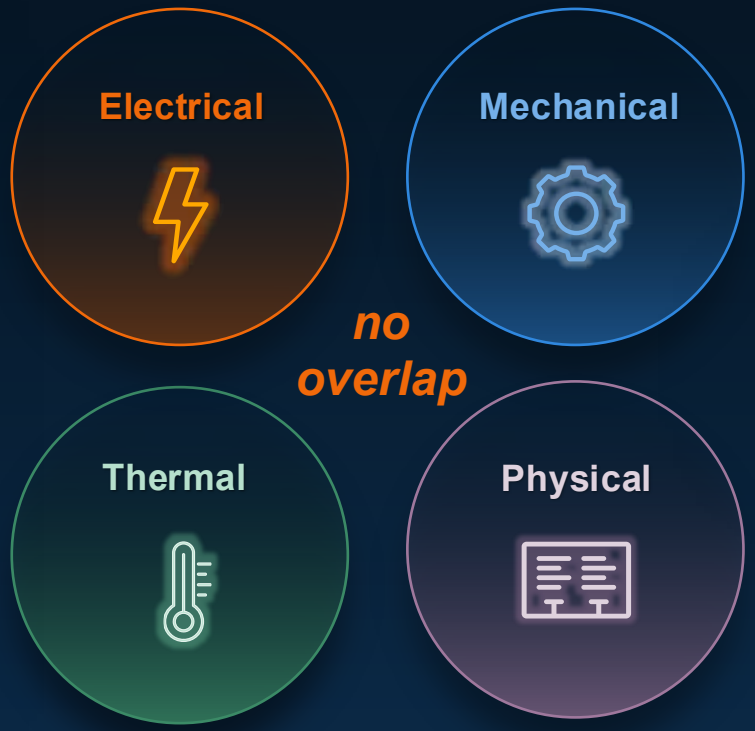
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System Requirements are Moving in Opposite Directions

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What the customer asks for

▲ **Input voltage**	Increasing
▼ **Output voltage**	Decreasing
▲ **Power**	Increasing
▼ **Physical space**	Constrained
◆ **Cost**	Always challenged



Electrical + Thermal + Mechanical + Physical
Nothing on the market closes all at once

And the problems only get harder across end markets and applications

AI Data Center
800V and higher → 6V or less

Industrial: Solid-State Transformer
13.8kV → 34.5kV

Automotive: xEV
400V → 900V+

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The Constraint has Changed.
So did we.

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FROM

SOLVING POWER

Efficiency • Conversion • Components • Scale



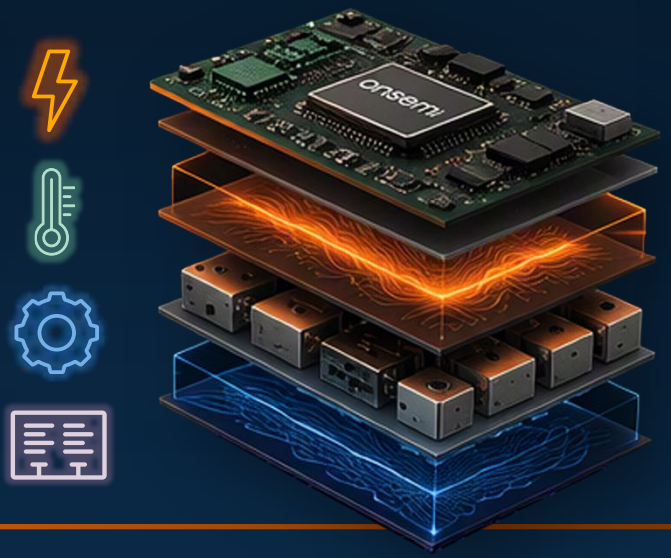
Power density is not solved by one device

It requires a different company

TO

SOLVING POWER DENSITY

Electrical • Thermal • Mechanical • Physical



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onsemi is a fundamentally different company for a fundamentally different problem: Power Density

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onsemi STRATEGIC ACTIONS

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STRONG TECHNOLOGY BASE

2021 | 2022 | 2023 | 2024 | 2025 | 2026 | And Beyond

GTAT
Acquisition

300mm East Fishkill
NY Fab
Acquisition

SWIR VISION
Acquisition

SiC JFET
Acquisition

VCORE
Acquisition

RISC-V
Acquisition

Synaptics
Acquisition

SiC MOSFET
Technology Development

Treo Platform
Technology Development

VERTICAL GaN
Technology Development

Embedded Power Platform
Technology Development

Advanced Material Deposition
Technology Development

LATERAL GaN
Technology Development

Silver Atena Power Systems
Acquisition

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Synaptics Extends the onsemi Portfolio…

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POWER

Efficient power conversion

- Silicon to wide-bandgap
- Power management
- Power protection

onsemi + Synaptics

SENSE

Perception of the physical world

- Image sensors
- Ultrasonic & Inductive position sensors
- HMI & Tactile sensing

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CONTROL

Precise actuation & control

- Analog & mixed-signal ICs
- Drivers
- Controllers

+ Synaptics

CONNECTED COMPUTE

Edge intelligence & connectivity

- Single pair ethernet
- AI-First Compute
- Connectivity: Wi-Fi / BLE / Thread

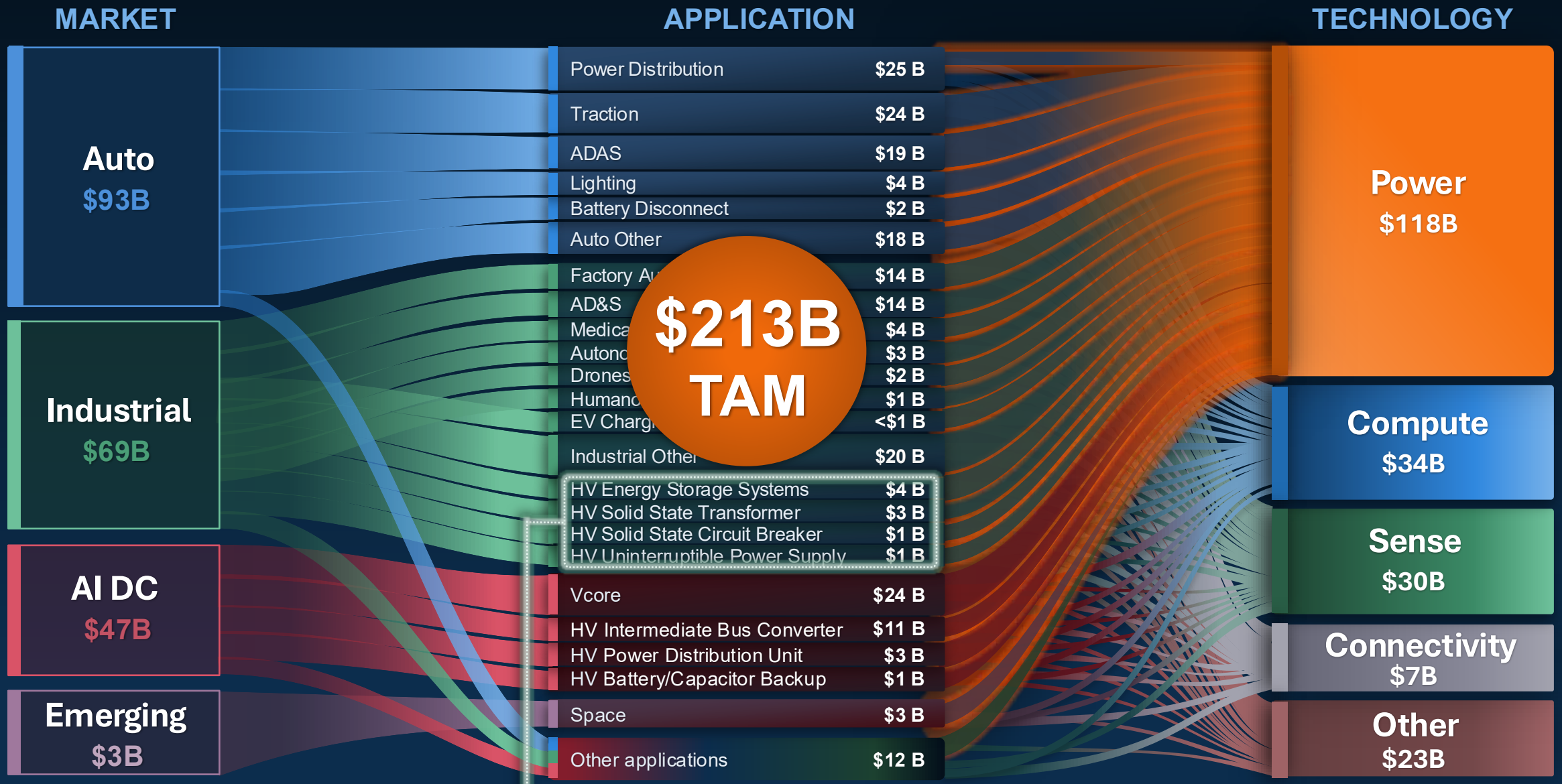
…completing the Four Pillars of Physical AI

Machines that sense, decide, act and adapt

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Every Market Converges on Power

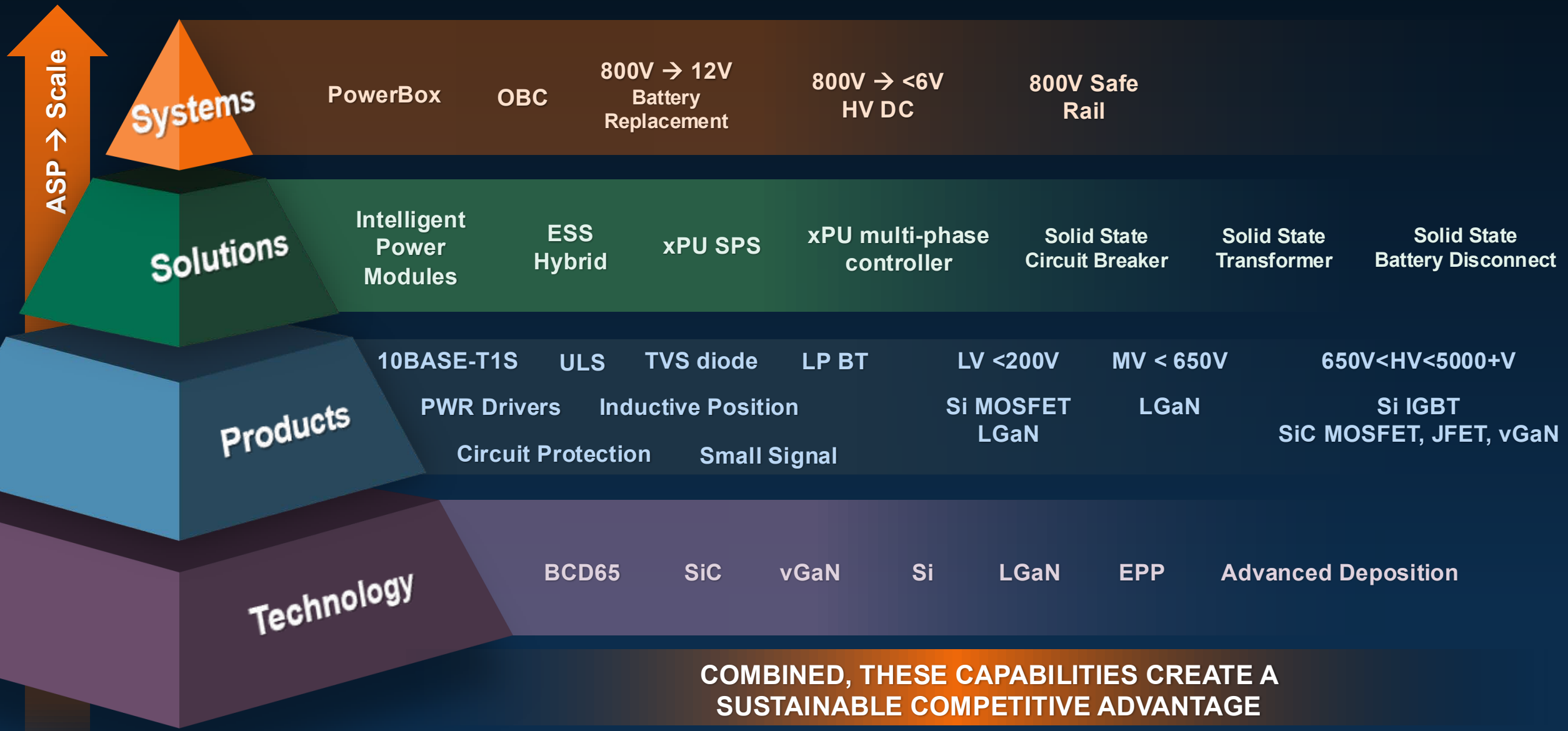
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AI Halo - $9B of industrial built to support data centers

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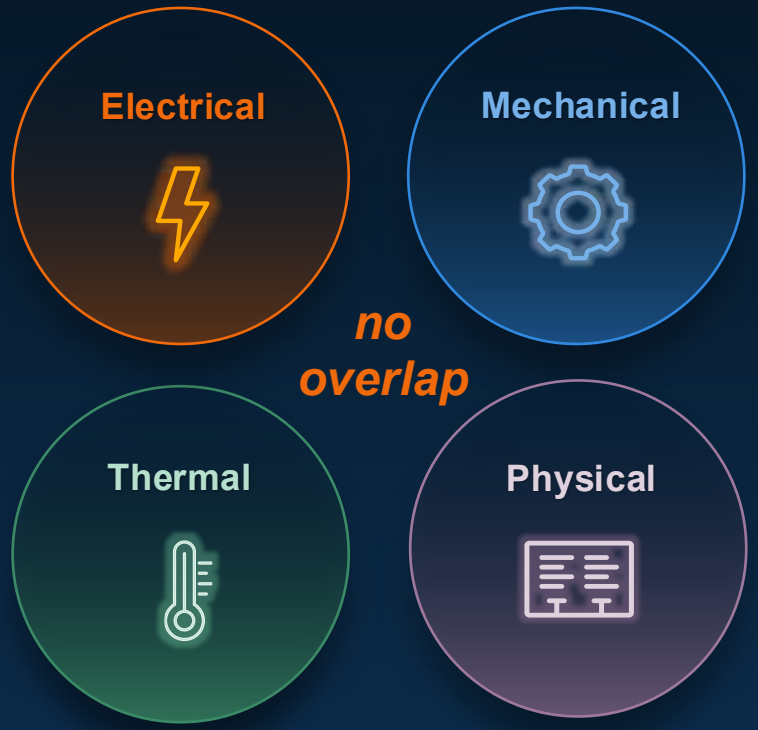
Delivering The Value Stack



COMBINED, THESE CAPABILITIES CREATE A SUSTAINABLE COMPETITIVE ADVANTAGE

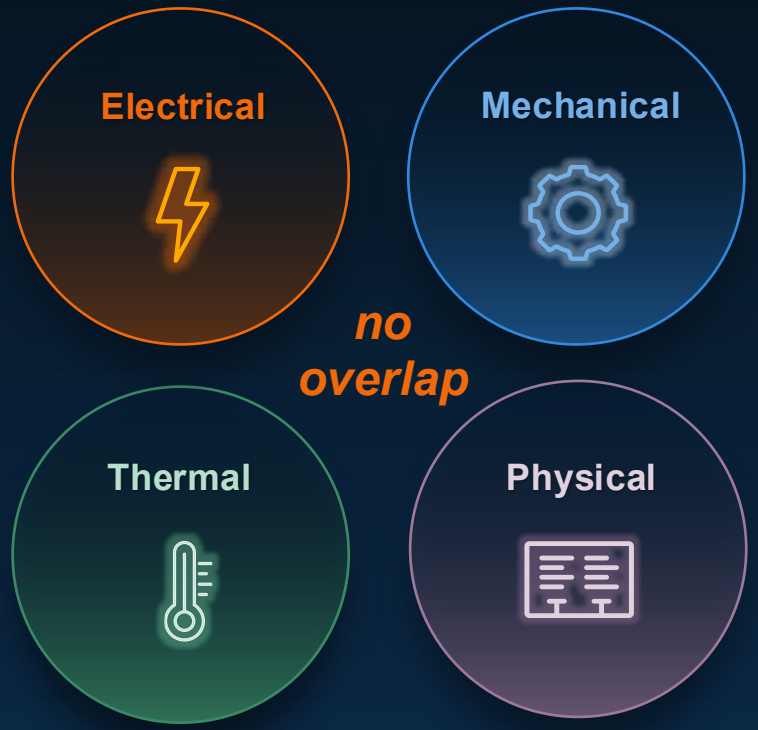
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We Must Change the Power Systems Paradigm…



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…by Introducing Technologies to Address the Constraints…



HV
THE DEVICE

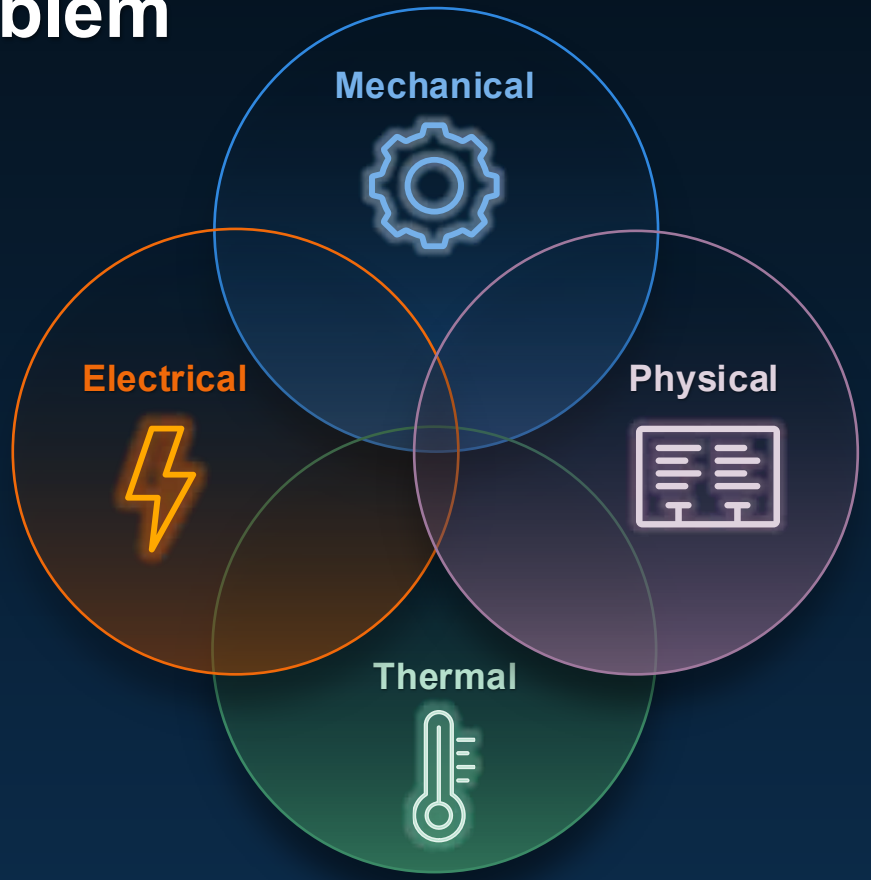
Treo
THE INTELLIGENCE

EPP
THE INTEGRATION

Supported by a complete portfolio of differentiated Power and Sensing technologies

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…And Creating the Disruption Necessary to Unlock the Power Density Problem



HV
THE DEVICE

Treo
THE INTELLIGENCE

EPP
THE INTEGRATION

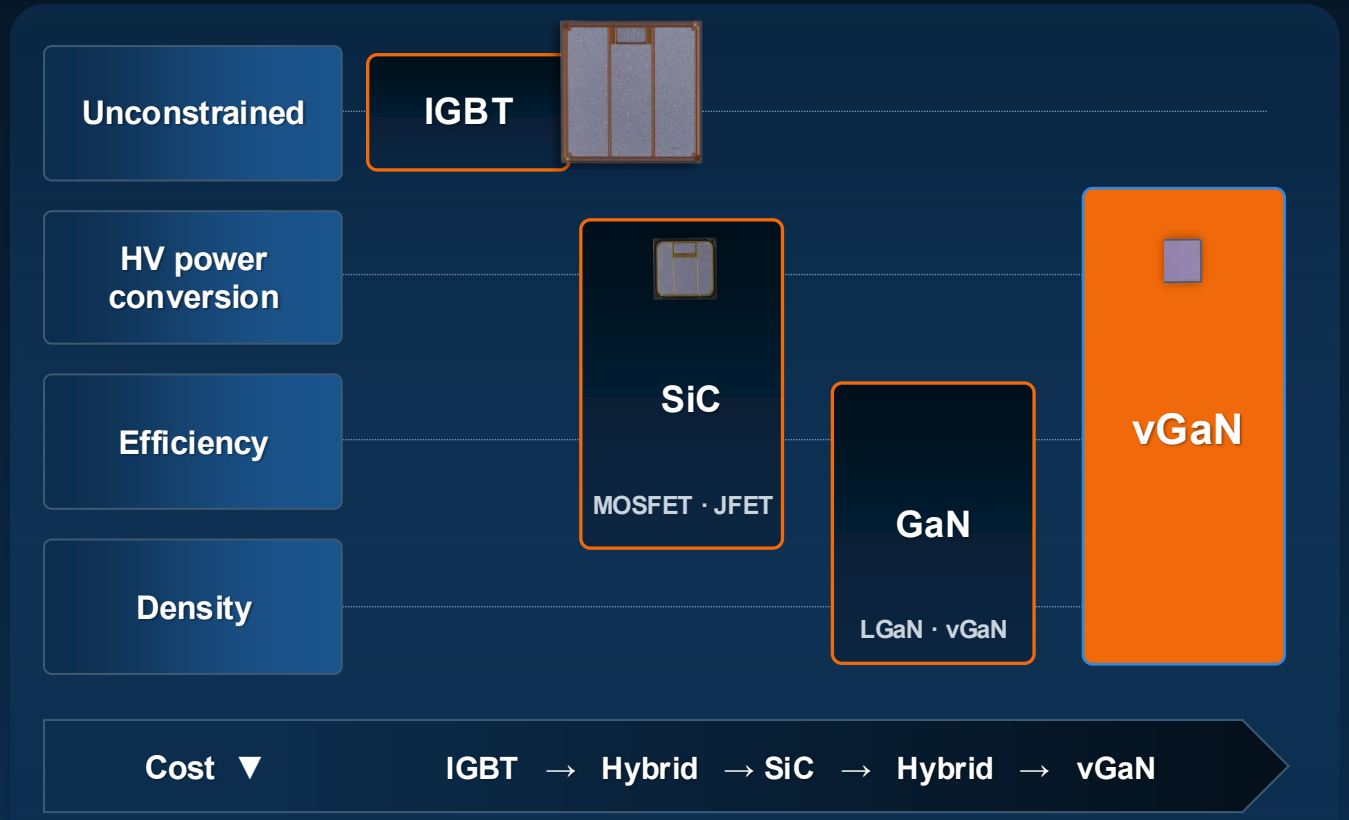
Supported by a complete portfolio of differentiated Power and Sensing technologies

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onsemi has Every HV Option to Close the Gap

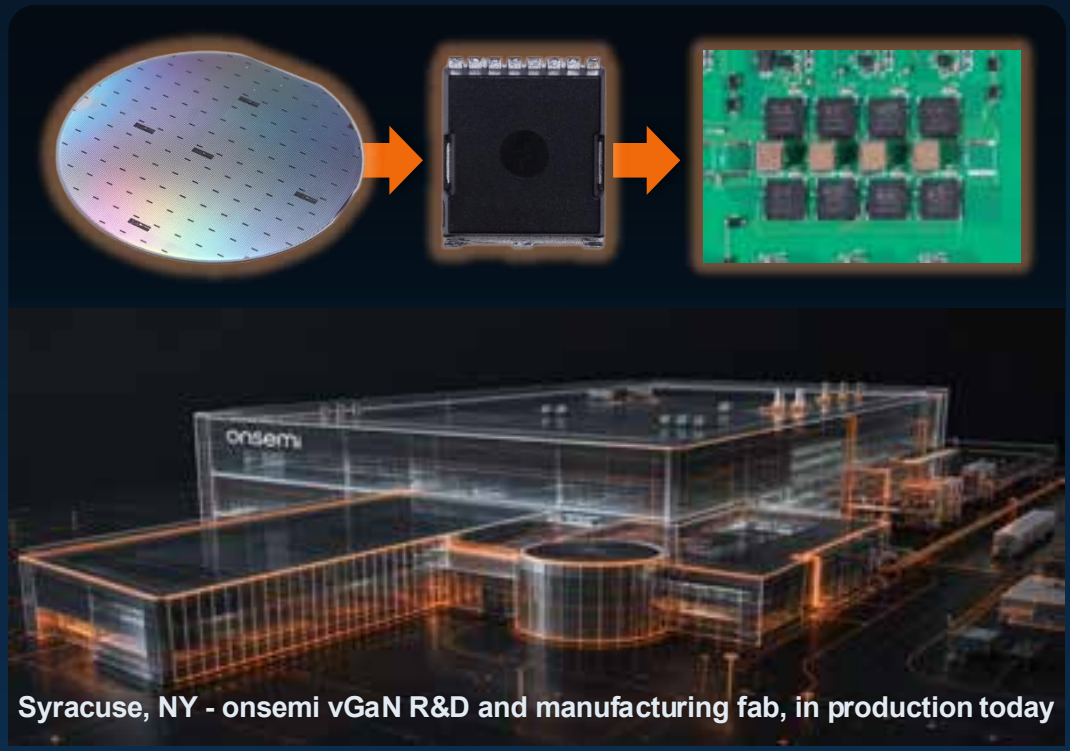
HV | Treo | EPP

Power and Sense Portfolio



onsemi's HV device portfolio has every option needed to optimize the customer solution

vGaN solution…And it's ready



Syracuse, NY - onsemi vGaN R&D and manufacturing fab, in production today

66,000 sq ft	20,000 sq ft	$40M+	$120M+
14-acre site	clean room	tools & machines	investment

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HV | Treo | EPP

Power and Sense Portfolio

Treo Platform

Communications Subsystem

Application-Specific Interfaces

Power Subsystem

- Power Control
- DC-DC
- Driver
- Power FET

Power Subsystem

- High-Performance AFE
- Low-Power AFE

Compute & System Resources Subsystem

- Compute
- Voltage/Clock
- Standard I/O
- Memory
- Test
- Peripherals

The **onsemi Treo Platform**

is the **most advanced** in the industry, **enabling winning** analog and mixed-signal products, for next generation applications

BCD 65nm Technology Process

Best performance & power
Advanced feature integration

Industry's Widest Voltage Range: 1 - 90V

Highest integration
Auto 48V transition

Modular Architecture

Broad **onsemi** portfolio
Fast time-to-market

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Treo Analog and Mixed-Signal Platform

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HV | Treo | EPP

Power and Sense Portfolio

Automotive | Industrial | AI / Client | Compute | Medical | Mass Market

2024
Products Sampling

- **Low-Power AFE ASIC**
  Medical
- **Ultrasonic Sensor ASIC**
  Automotive
- **Test Equipment Signal Processor ASIC**
  Industrial
- **10BASE-T1S MAC-PHY**
  Automotive, Industrial
- **Multi-Phase Controller**
  AI / Client
- **LDO Regulators**
  Mass Market
- **Voltage Level Translators**
  Mass Market
- **Bus Switches / Muxes**
  Mass Market

2025
Products Sampling

- **10BASE-T1S RCP**
  Automotive, Industrial
- **Smart LED Driver Chipset**
  Automotive
- **Ultrasonic Base Product**
  Automotive
- **2-Ch Low-Power AFE ASIC**
  Medical
- **LIN Transceiver**
  Automotive
- **Platform MCU**
  Automotive, Industrial, AI / Client, Mass Market
- **Precision Current-Sense / Comparators**
  Automotive, Industrial, Mass Market
- **Expanded LDO Portfolio**
  Automotive, Industrial

2026
Products Sampling

- **48V SmartFET High-Side Drivers**
  Automotive
- **Isolated SiC Gate Driver**
  Automotive / AI Data Center
- **High-Perf Ultrasonic Sensor**
  Automotive
- **Inductive Position Sensors**
  Auto (E-Pedal/Steer)
- **Rain / Light Sensor Interface**
  Automotive
- **Ideal Diode Controller**
  Automotive, Industrial, Compute
- **ReRAM Non-Volatile Memory**
  Automotive, Industrial, Compute
- **Expanded Current-Sense**
  Automotive, Mass Market
- **Additional Voltage Translators**
  Mass Market
- **Switched-Cap Converter + LDO**
  Automotive, Industrial

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Introducing onsemi's Embedded Power Platform

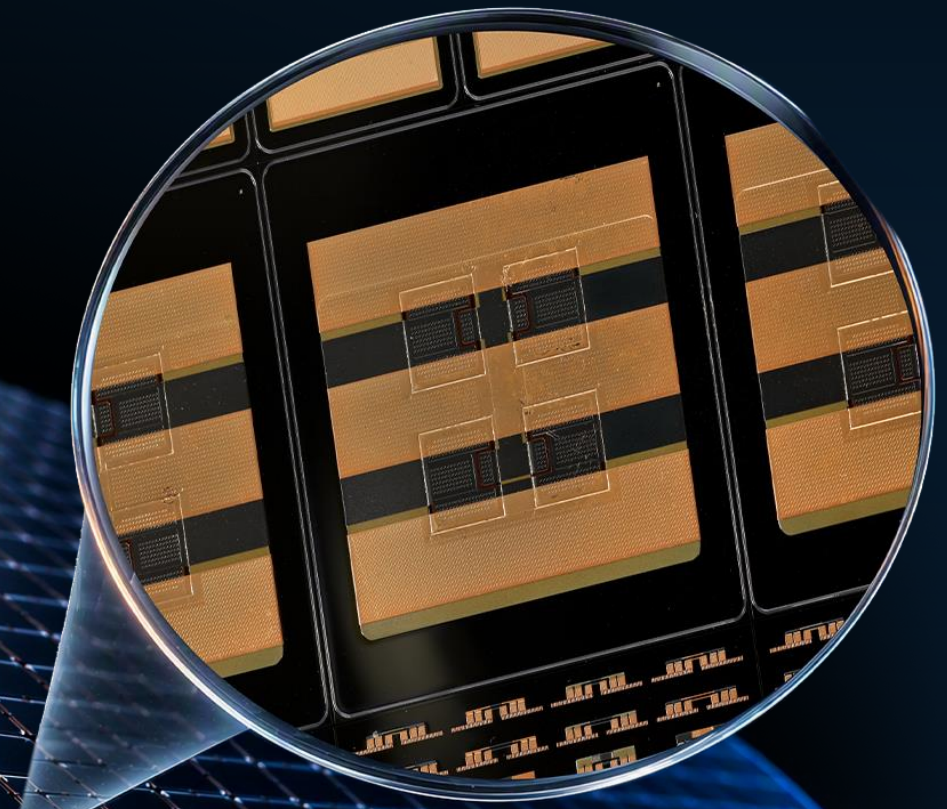
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The silicon becomes the system.

EPP is the breakthrough that creates a new category of power systems.

3–5×	30%	12 in.	4 MOS
UNMATCHED POWER DENSITY	HIGHEST SYSTEM VALUE	STANDARD MANUFACTURING	FASTEST TIME TO MARKET

- ✓ BEST-IN-CLASS INDUCTANCE
- ✓ SUPERIOR THERMAL PERFORMANCE



Embedded Power Platform (EPP) uses the silicon wafer itself as the package, embedding heterogeneous die to deliver electrical, mechanical and thermal performance simultaneously, solving the density problem.

Not a product. A platform.

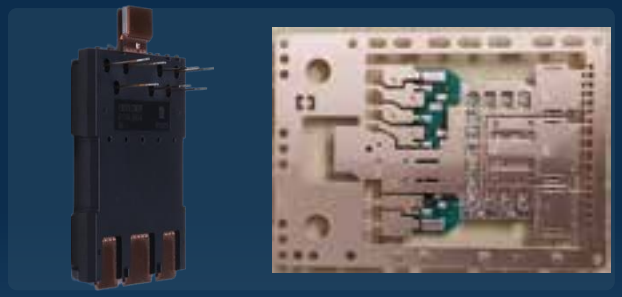
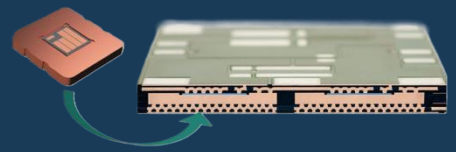
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EPP Leapfrogs PCB Embedded Power

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HV | Treo | **EPP**

Power and Sense Portfolio

EVALUATION CRITERIA	Yesterday's solutions Lead-frame & DBC substrate (B2S) Available today	State-of-the-art Panel / S-Cell PCB embedding Available today	onsemi EPP Embedded Power Platform Sampling today
			
Power density (area vs. B2S)	1x	1.3x	**3x to 5x**
System cost (vs. B2S)	1.0	1.1	**0.7 – 0.8**
Stray inductance	Medium	Low	**Lowest**
Thermal path	Bottom-side · 4 W/mK	Bottom-side · 0.4 W/mK	**Dual-side · 148 W/mK**
Device performance	1.0	+5%	**+30%**
Manufacturing	Custom · high CapEx	Custom · high CapEx	**12″ Si fab · low CapEx**
Idea → production	12 months (6+6)	12 months (6+6)	**4 months**

Embedded Power Platform obsoletes the State-Of-The-Art

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Delivering Value to Customers Already

HV | Treo | **EPP**

Power and Sense Portfolio

< 48 hours

1 Customer input

Size · Voltages · efficiency

2 EPP Design Studio

Electrical, thermal and mechanical simulation · multi-technology

< 5 days

3 Studio output

Design · datasheet · validated models

4 Customer system modelling

System design and concept complete

< 3 months

5 No custom back-end

No new CapEx or custom tooling to bring up

6 Interposer manufacturing

12″ silicon fab · standard process

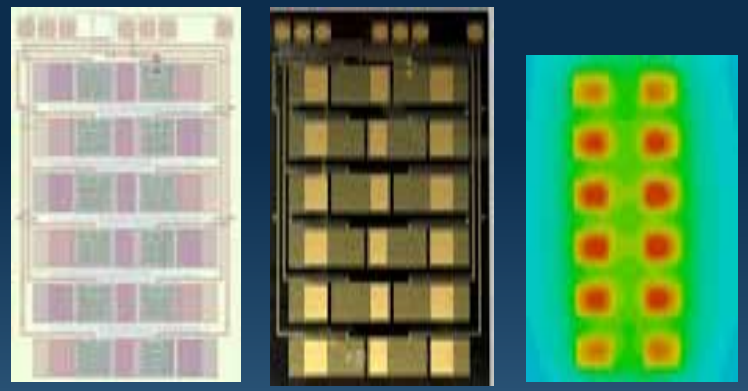
Customer / project dependent

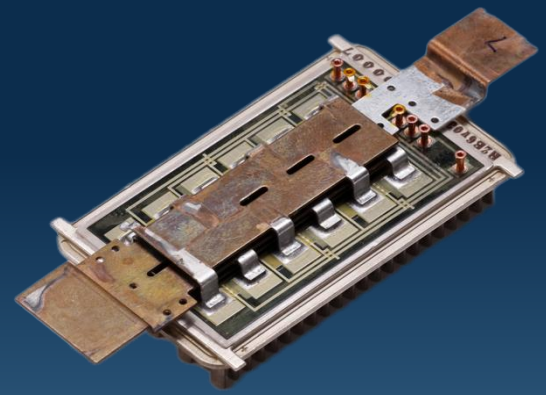
7 System integration

Validation at the customer, on the customer's schedule

8 Production

Wafer-level test · standard flow





SUBARU

Industrial Customer

AI DC Customer

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onsemi Differentiation

Solving Problems with a Complete and Unique Suite of Capabilities

TECHNOLOGY NEEDED	onsemi	Peer 1	Peer 2	Peer 3	Peer 4
IGBT	✓	✓	×	✓	×
Silicon MOSFET	✓	✓	✓	✓	×
SiC MOSFET	✓	✓	×	✓	●
SiC JFET	✓	✓	×	×	×
Lateral GaN	✓	✓	✓	✓	✓
Small Signal and Protection	✓	×	×	×	×
Vertical GaN	✓	×	×	×	×
Treo (BCD 65nm, 1V-90V)	✓	●	●	●	×
Embedded Power Platform	✓	×	×	×	×

UNIQUE AND DEFENSIBLE COMPETITIVE POSITION

Power
1500+ patents

Vertical GaN *(GaN-on-GaN)*
Syracuse-built, 180+ patents,
700 V & 1200 V sampling.

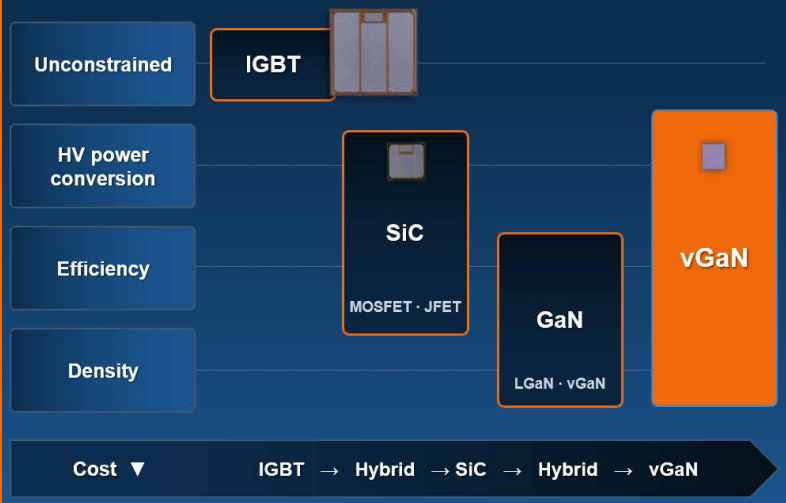
EPP
EFK-built, 60+ patents.
Sampling Auto and AI DC

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The constraint is a system constraint and must be answered at the **device**, the **intelligence** and the **integration** layer

HV
THE DEVICE

Technology for every power problem



TREO
THE INTELLIGENCE

Analog and mixed-signal platform

Treo Platform

Communications Subsystem

Application-Specific Interfaces

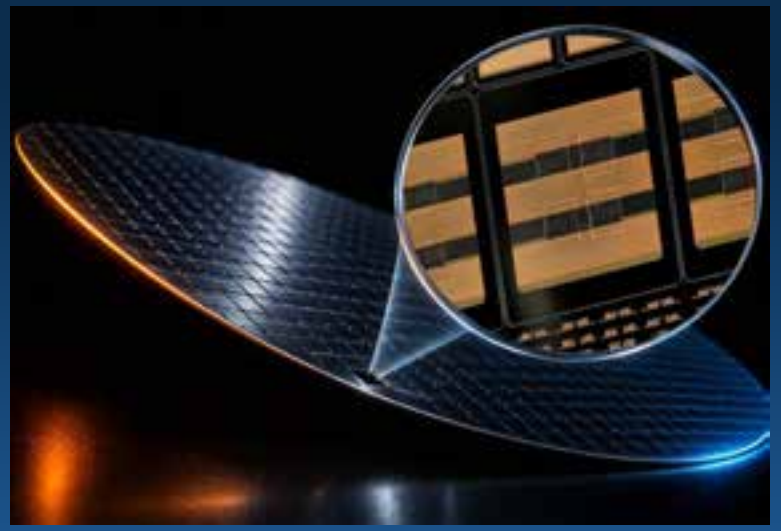
Power Subsystem		Power Subsystem
Power Control	DC-DC	High-Performance AFE
Driver	Power FET	Low-Power AFE

Compute & System Resources Subsystem

Compute	Voltage/Clock	Standard I/O
Memory	Test	Peripherals

EPP
THE INTEGRATION

Silicon as the system



The requirements do not converge on their own

onsemi makes them converge. We solve **Power Density** at every level.

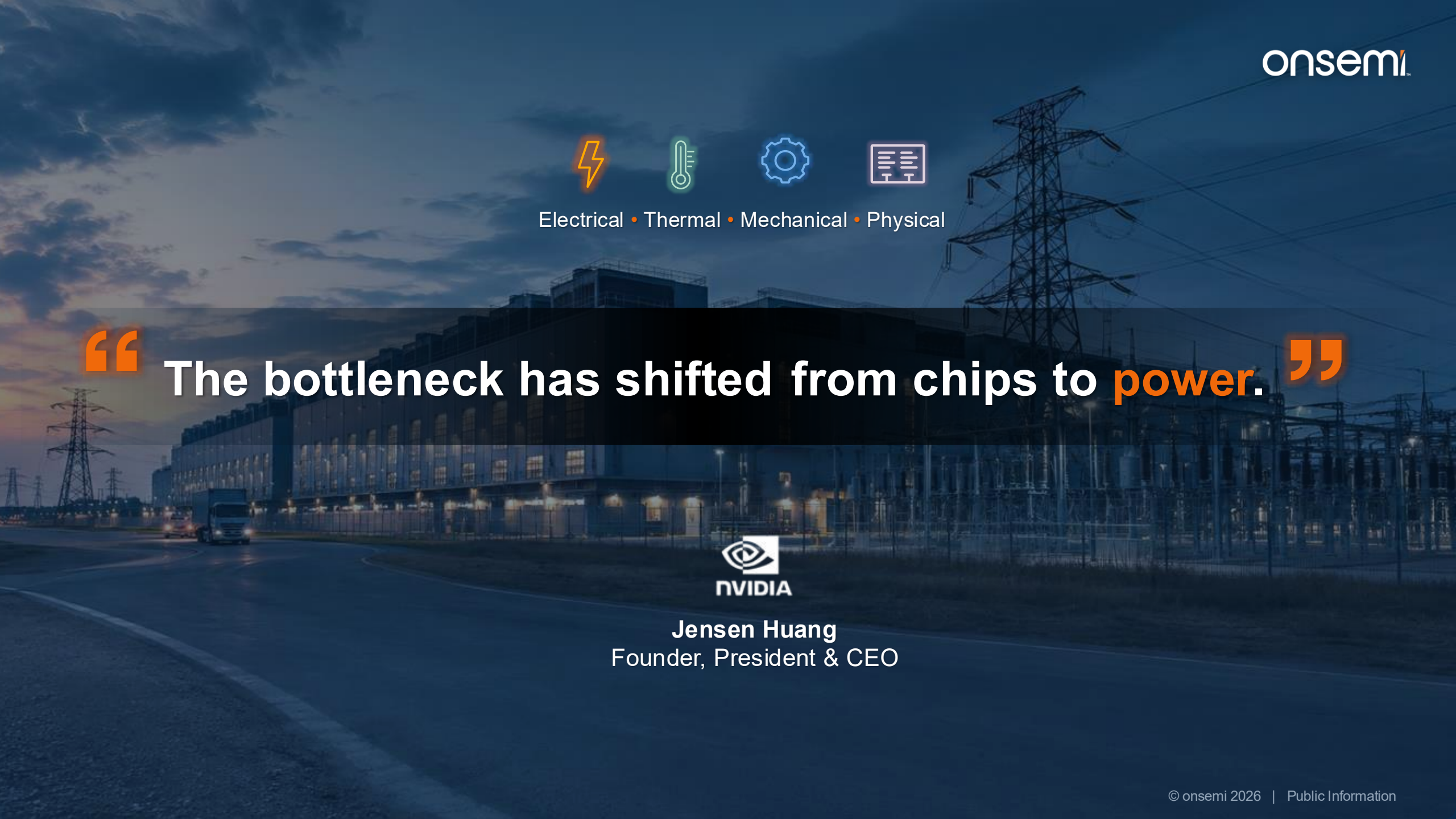
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onsemi: Powering the AI Revolution

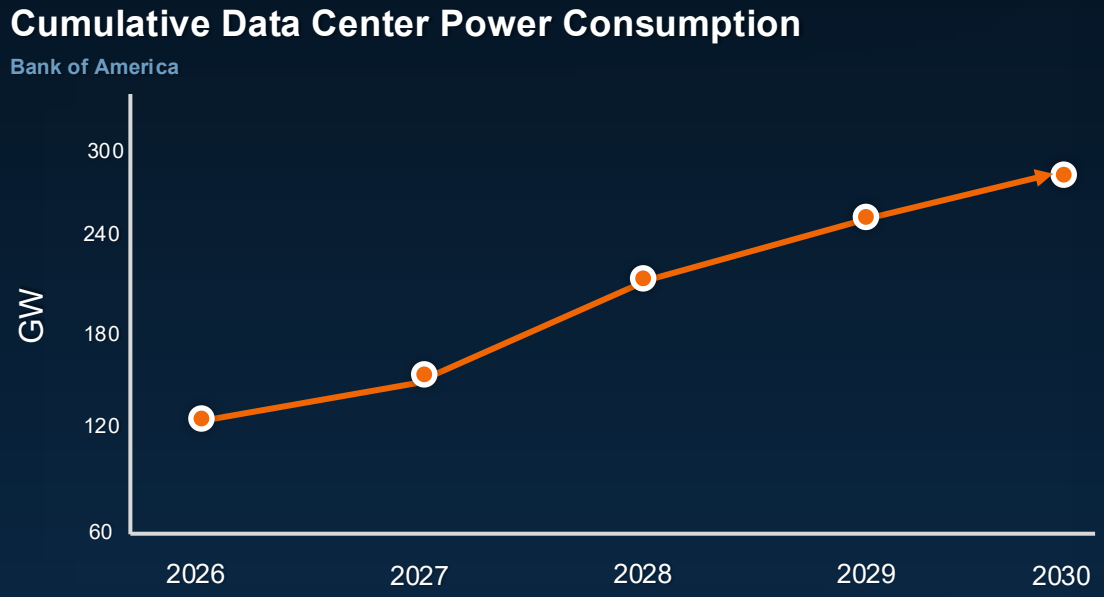
Achyut Shah
Group President, Power Solutions Group



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Increased Power Demand Creates Architectural Challenges

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NVIDIA

"800 VDC architecture: a single AC-to-800VDC conversion, distributed and used directly by the compute rack."

Goldman Sachs

"1,000 homes of power in a filing cabinet."

"Power, not GPUs, is the limiting factor for AI data centers… the power density challenge is creating a fundamental architectural crisis at the rack level. The companies that solve this first will shape the competitive landscape for years to come."

– Roland Berger

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Power Density Redefines Economics of Compute

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Less real estate



More tokens/$$



Less water used

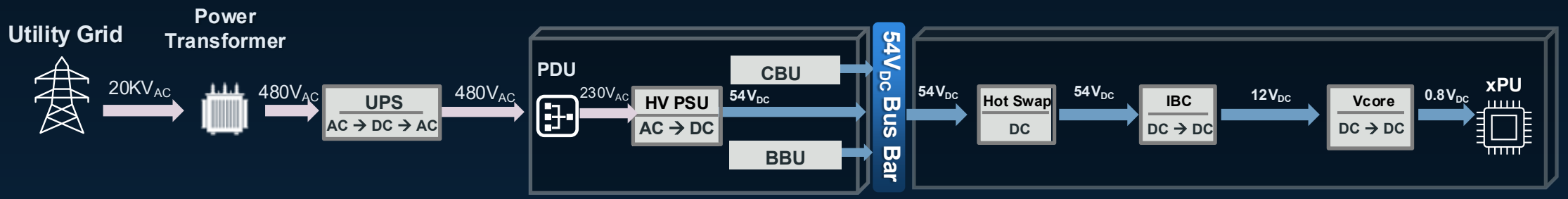
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xPU Power Increase Drives Move to High Voltage

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AC & Low Voltage Distribution and Conversion

Lateral Vcore

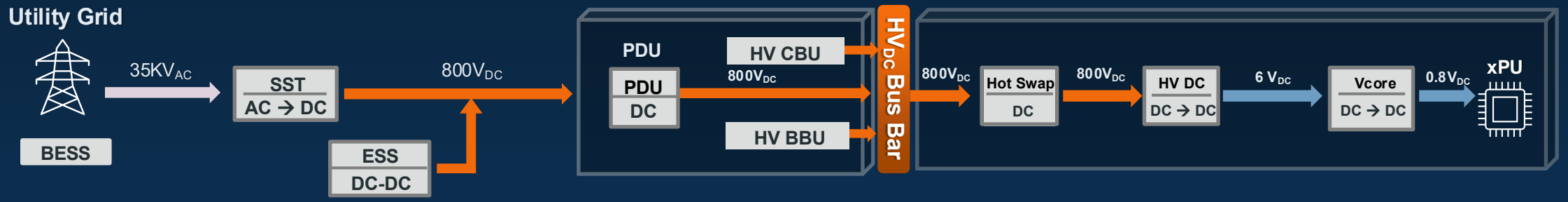


1kW xPU

Mechanical Transformer; Low Voltage Storage & Protection

High Voltage DC Distribution and Conversion

Vertical Vcore -VPD



5kW+ xPU

Solid State Transformer; High Voltage Storage & Protection

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High Voltage Reaches the Core – Content Multiplies











$15K
per rack

Today

$115K
per rack

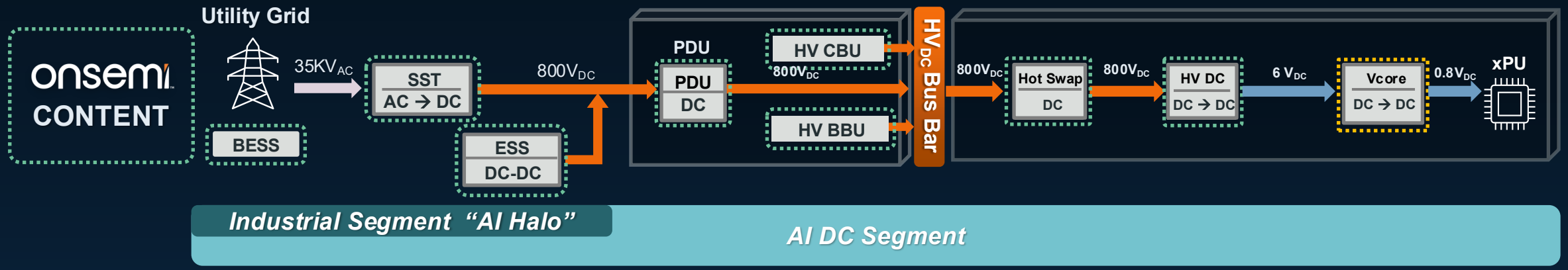
2030

Low Voltage

High Voltage

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Grid to Core High Voltage Plays to Our Strength





More Power, Limited Space

More High Voltage Content

More Energy Storage & Load Balancing

Mechanical to Semiconductor Content

More Control, Intelligence, Safety

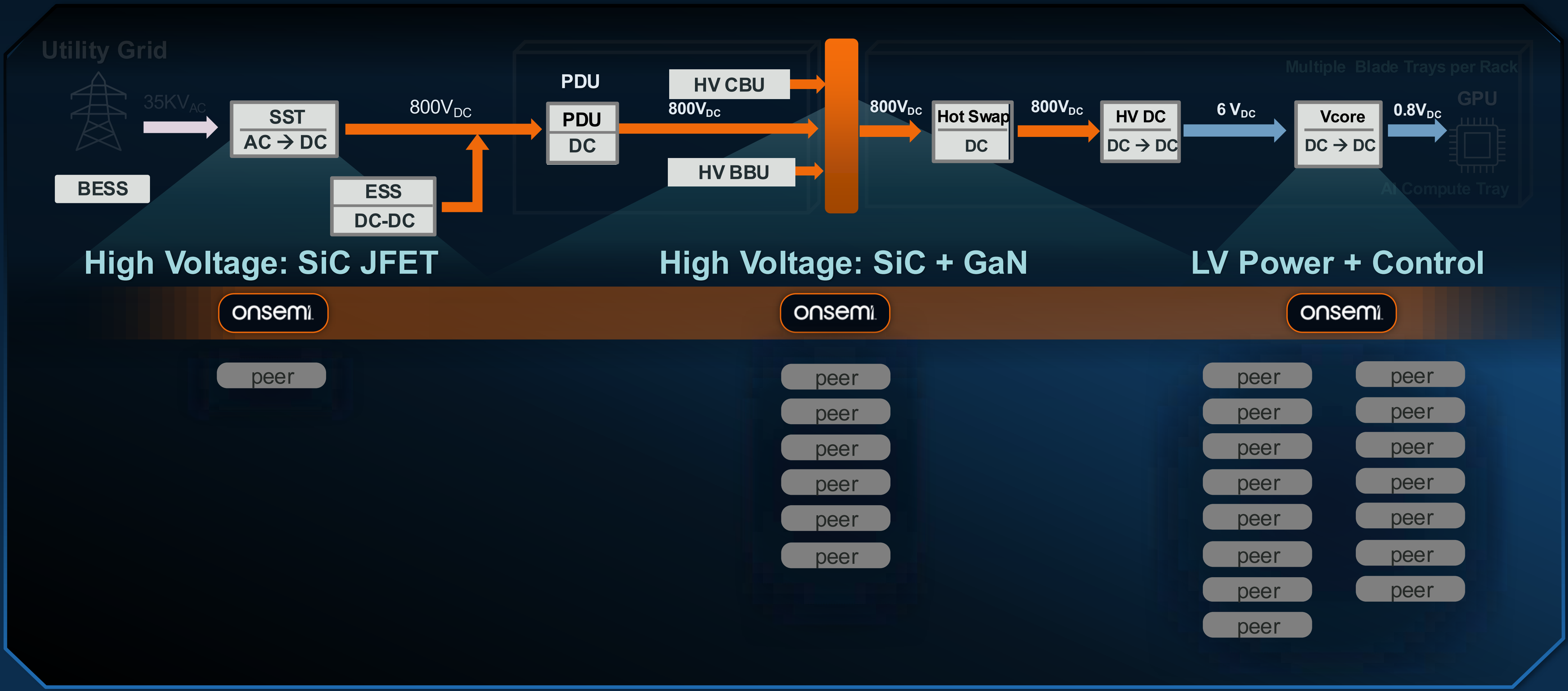
Multi-technology capabilities required to solve the power density challenge

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As Technology Breadth Grows, Competitor Field Shrinks

HV | Treo | EPP

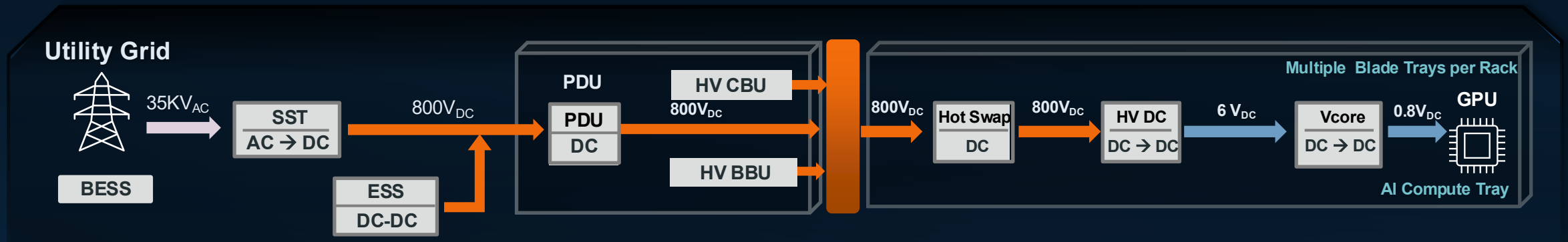
Power and Sense Portfolio



Win with Capability Breadth + Technology Differentiation

HV | Treo | EPP

Power and Sense Portfolio



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High Voltage: SiC JFET

High Voltage: SiC + GaN

LV Power + Control

Proven leadership across technology breadth

+

HV vGaN

EPP

Innovation Breakthrough

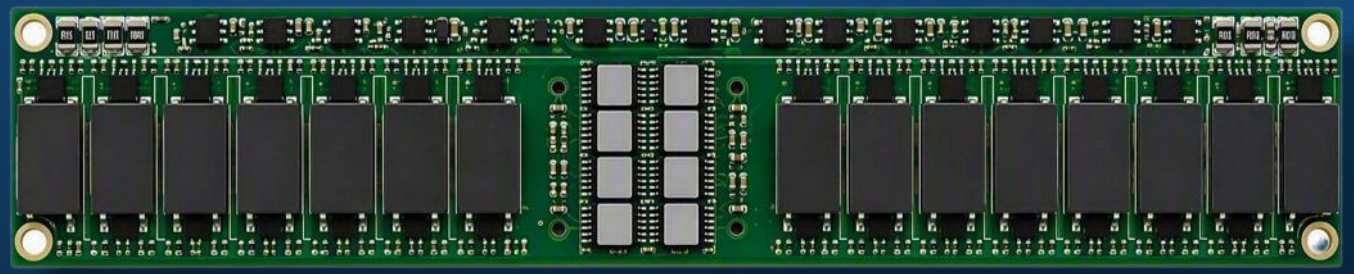
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vGaN Enables Highest Density 800V → 6V IBC

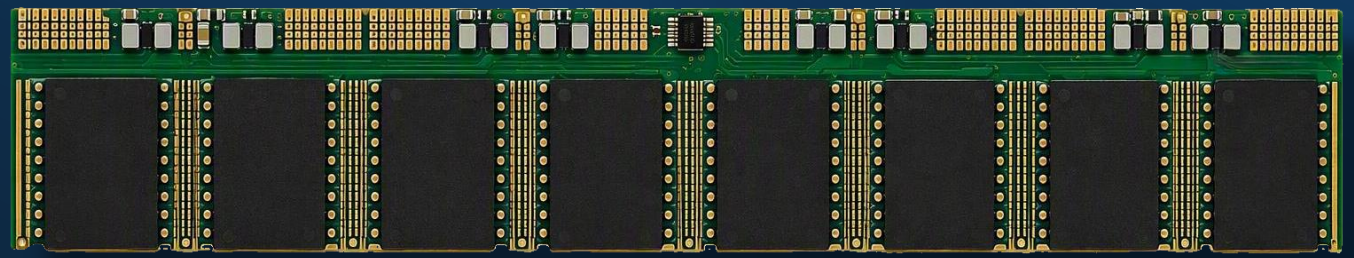
HV | Treo | EPP

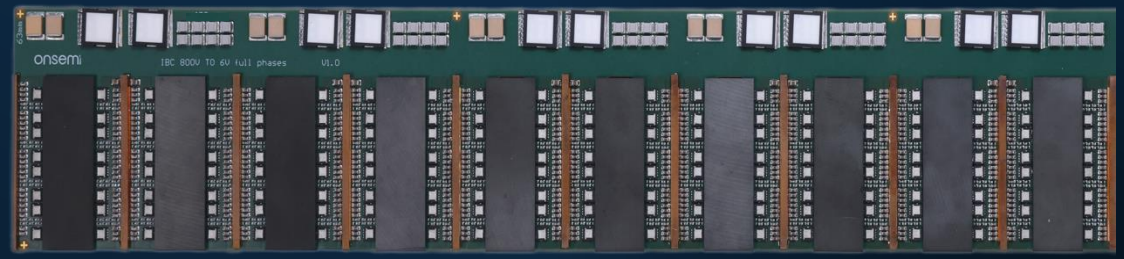
Power and Sense Portfolio

Competitor 1



Competitor 2



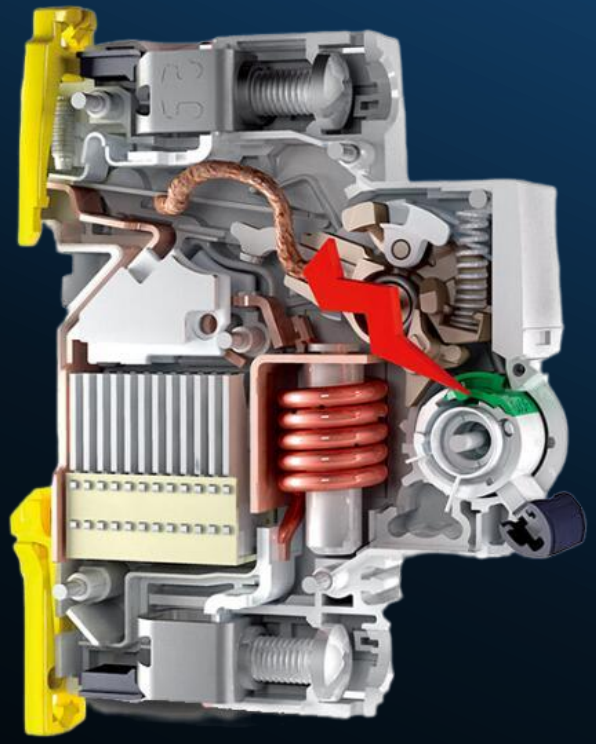


vGaN + Unique magnetics
= 20% smaller size

Higher Power density = More compute in Rack = Lower Cost per token

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Mechanical to Solid State Fault Protection



Mechanical Circuit Breaker



Industry-Standard
Solid State Circuit Breaker

High Voltage Architecture needs multiple Fault Protection points

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EPP + SiC JFET: Redefining the Density Benchmark

HV | Treo | EPP

Power and Sense Portfolio



Industry-Standard SSCB



Over 50% Smaller

EPP SSCB

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EPP + SiC JFET: Redefining the Density Benchmark

HV | Treo | EPP

Power and Sense Portfolio

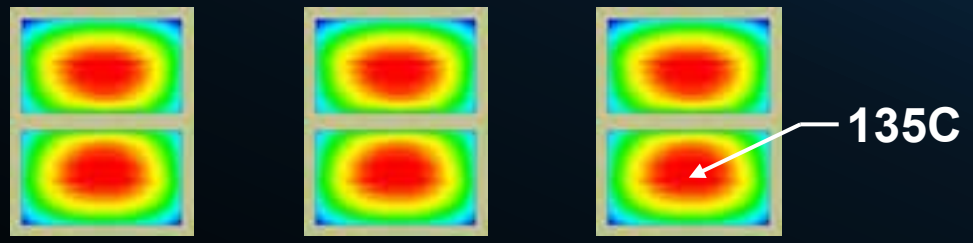




Over 50% Smaller

Industry-Standard SSCB

EPP SSCB





20% cooler

Smaller size + Less cooling = Better TCO

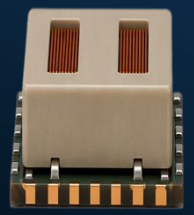
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EPP Enables Highest Vcore Power Density

HV | Treo | EPP

Power and Sense Portfolio

2 A/mm²



Z = 5 mm
with inductor

Available now

Lateral Power Delivery
2-Phase SPS + Inductor

>3 A/mm²



SPS in EPP

Z = 2 mm
With inductor

Available 2027

Vertical Power Delivery
onsemi enabled 4-Phase VPD
In partnership with module vendors

New Vcore Win 2026

EPP enabled SPS

Digital multi-phase control

Unique inductor design

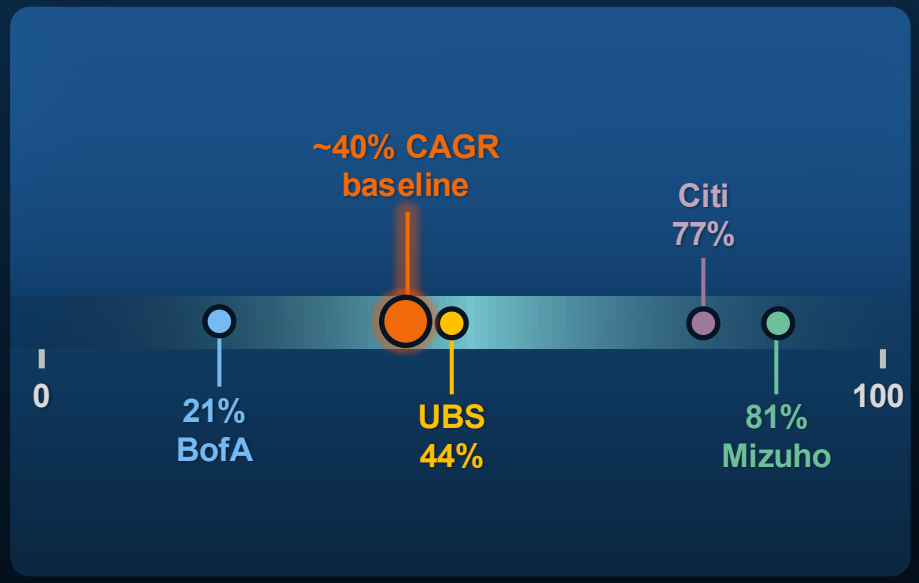
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Higher Power Density → Better Customer TCO → Revenue & Margin Growth

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AI DC TAM CAGR

Growth estimates vary
2026 – 2030



Our technology innovations allow us to significantly outgrow the market

AI DC Revenue

>2X in 2026 **2X in 2027**

Long-term Growth

+ 10 pts
above market

50%+
revenue CAGR
2026-2030

~5X AI DC Revenue Growth

>$500M (2026) → >$2.5B (2030)

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AI turns power into **one** connected system.

The prize grows
The field shrinks

onsemi

Solves the **toughest challenges**

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Expanding the Core: Automotive and Industrial

Sudhir Gopalswamy
Group President, Analog & Mixed-Signal and Intelligent Sensing Groups

Expanding the Core

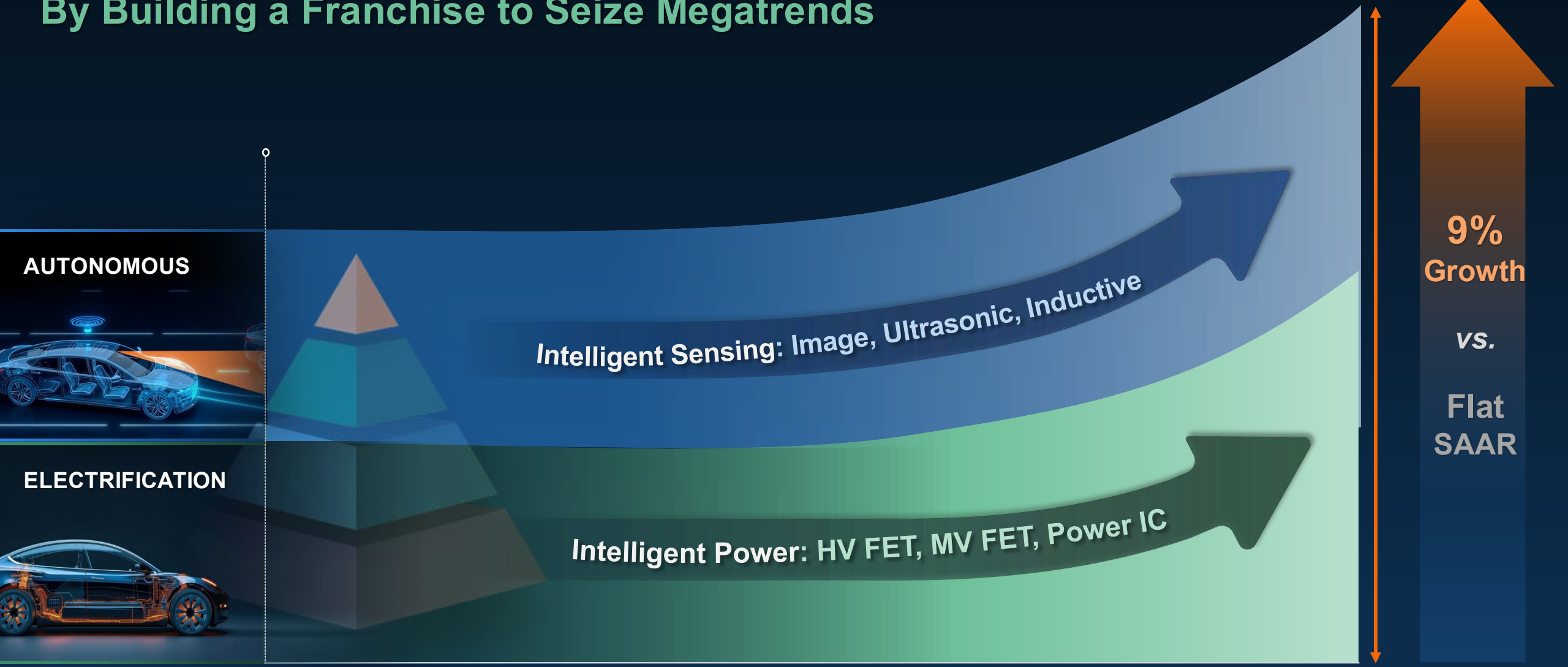


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We Have Outgrown Automotive SAAR by 9%

By Building a Franchise to Seize Megatrends

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We Will Continue to Outperform SAAR by 9%

While Shifting to Higher Value

SDV/ZONAL

$9B TAM



AUTONOMOUS

$15B TAM



ELECTRIFICATION

$47B TAM



Intelligent Nodes

Central “Brain”

End-end Ethernet

L4

L3

L2

Efficiency targets

Ultra-fast charging

EV penetration

Today ----------→ 2030

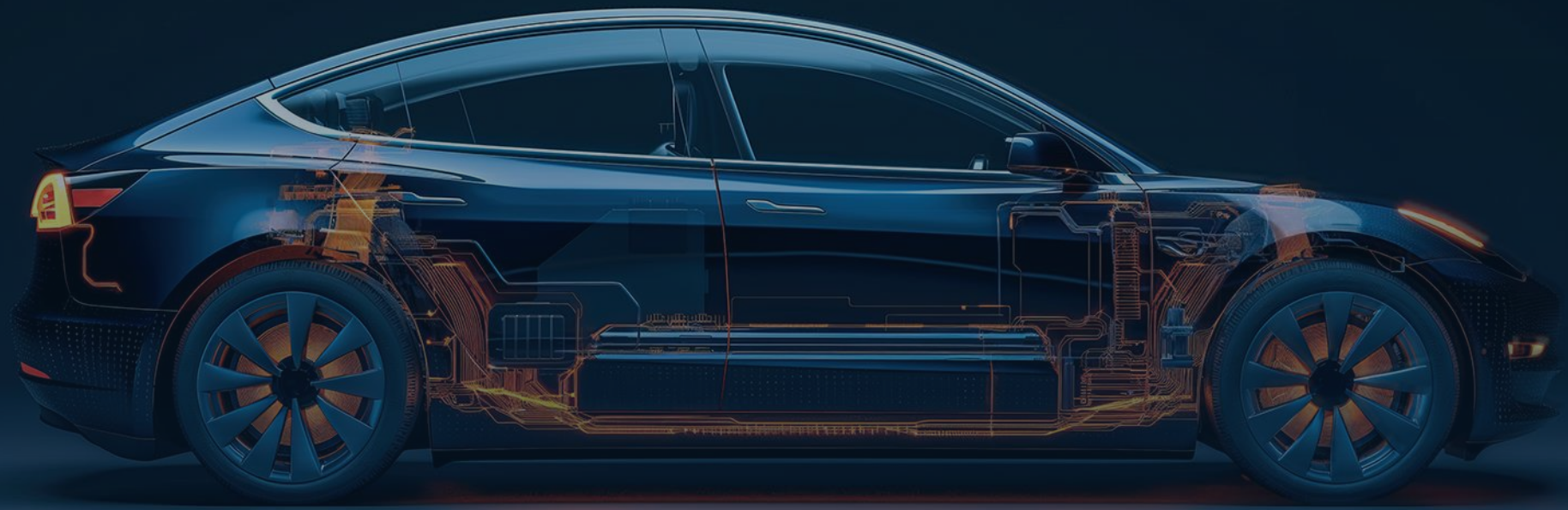
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Intelligent Power Growth Plan

Extend SiC Technology Leadership

Expand System Value with Treo Power ICs

Change the Game with EPP



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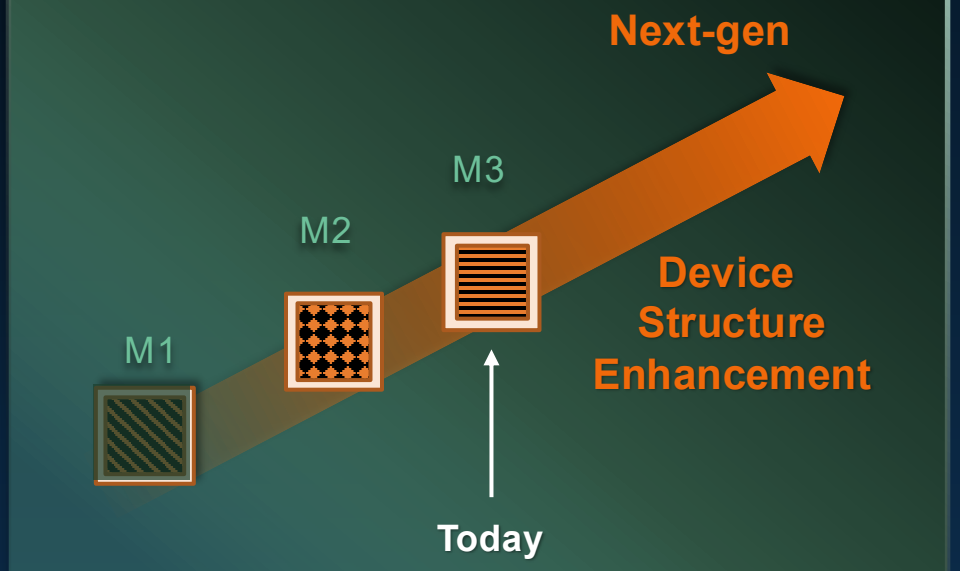
SiC Leadership Provides Growth Foundation

We Will Continue to Raise the Bar

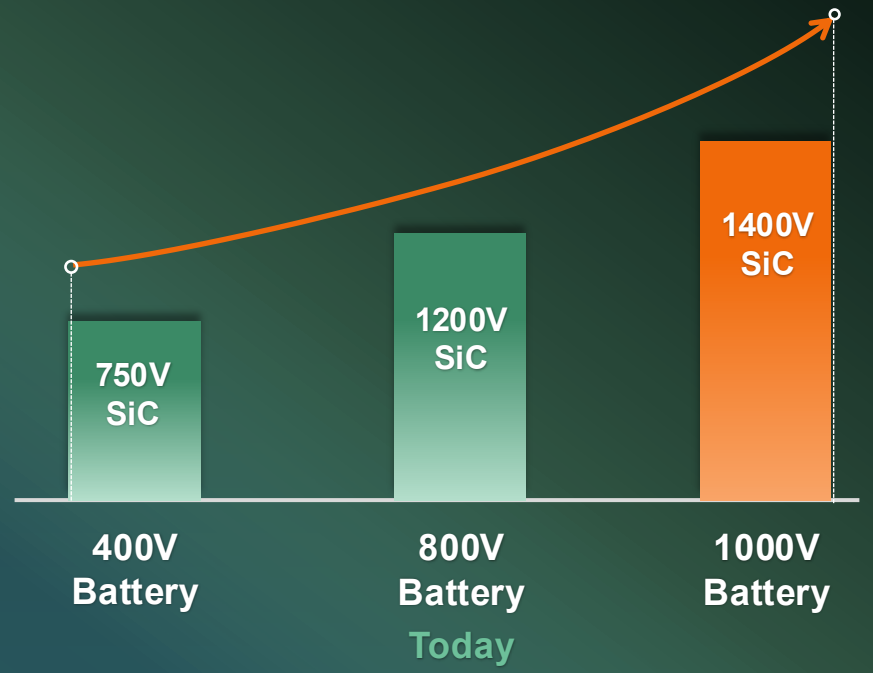
HV | Treo | EPP

Power and Sense Portfolio

SiC performance: +25% per generation



Extend to 1400V SiC



ELECTRIFICATION

$47B TAM



Customer Value

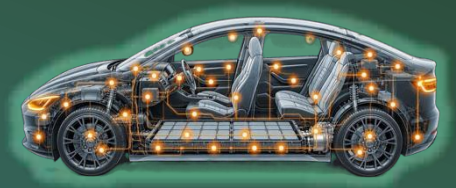
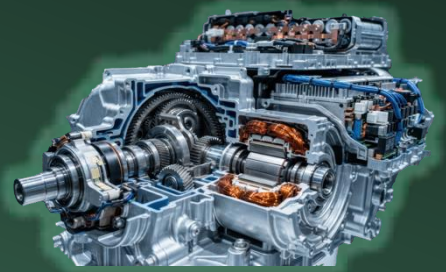
- Efficiency → Range or System Cost
- Power Density → Horsepower or System Cost
- Higher Voltage → Faster Charging

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Expand System Value: Treo Power ICs

HV | Treo | EPP

Power and Sense Portfolio

Power Tree	Power Tree	Traction & OBC	Front/Rear Lighting	"Brain"
				
Power Protection	LDOs	Current Controllers	LED Drivers	SPS, DC-DC Controllers

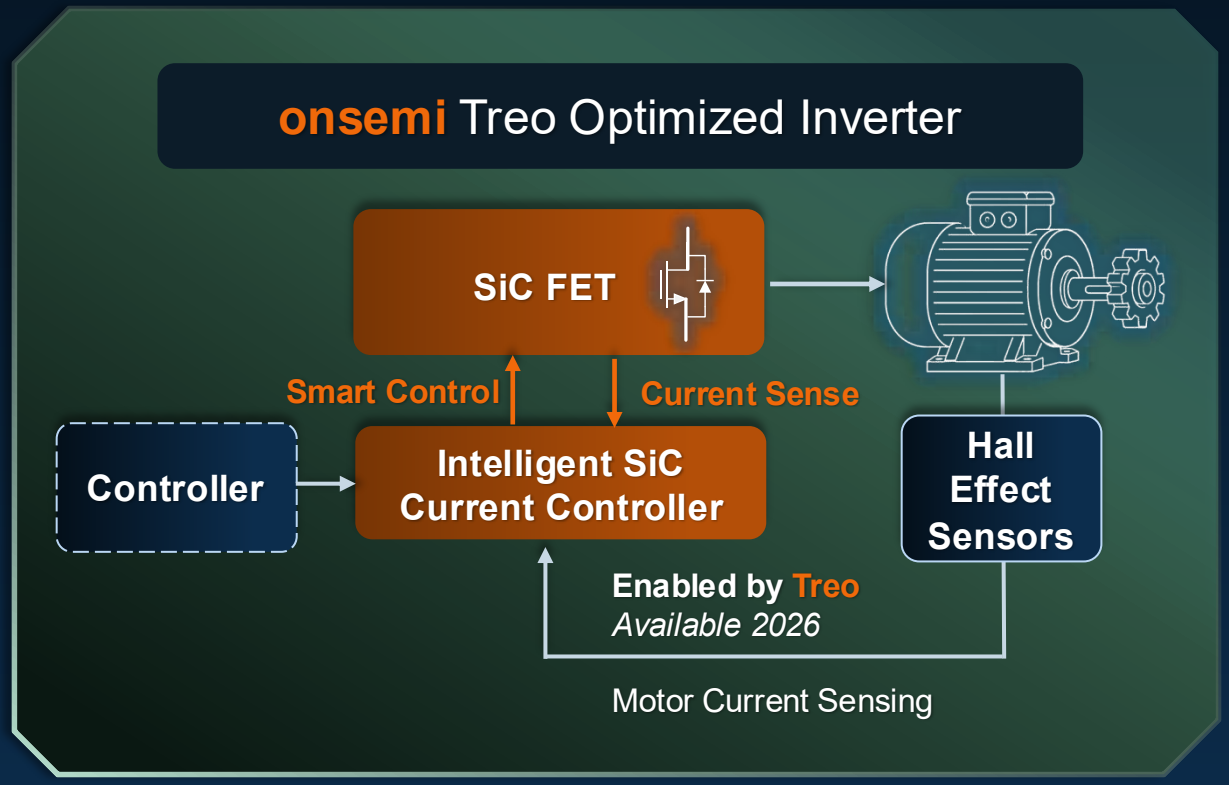
Enabled by Treo

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Intelligent Treo SiC Current Controller

HV | Treo | EPP

Power and Sense Portfolio



1-Gen SiC Boost

5% BOM Savings

ELECTRIFICATION

$47B TAM



Customer Value

Efficiency → Range or System Cost

Power Density → Horsepower or System Cost

Integration → System Cost

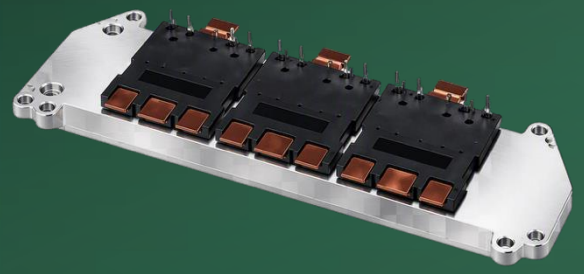
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EPP Transforms Inverter Solutions

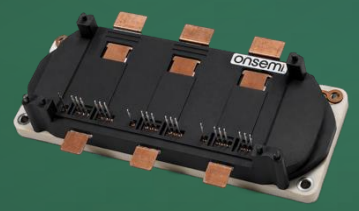
HV | Treo | EPP

Power and Sense Portfolio

State-of-the-art



EPP



Available 2026

4x Power Density

High end

1 Inverter Platform

Low end

15% Power Losses

ELECTRIFICATION

$47B TAM



Customer Value

Power Density → Smaller, Lighter → Flexibility

Scalability → Lower R&D & Manufacturing Cost

Efficiency → Range or System Cost

Full System → Fast Time-to-Market

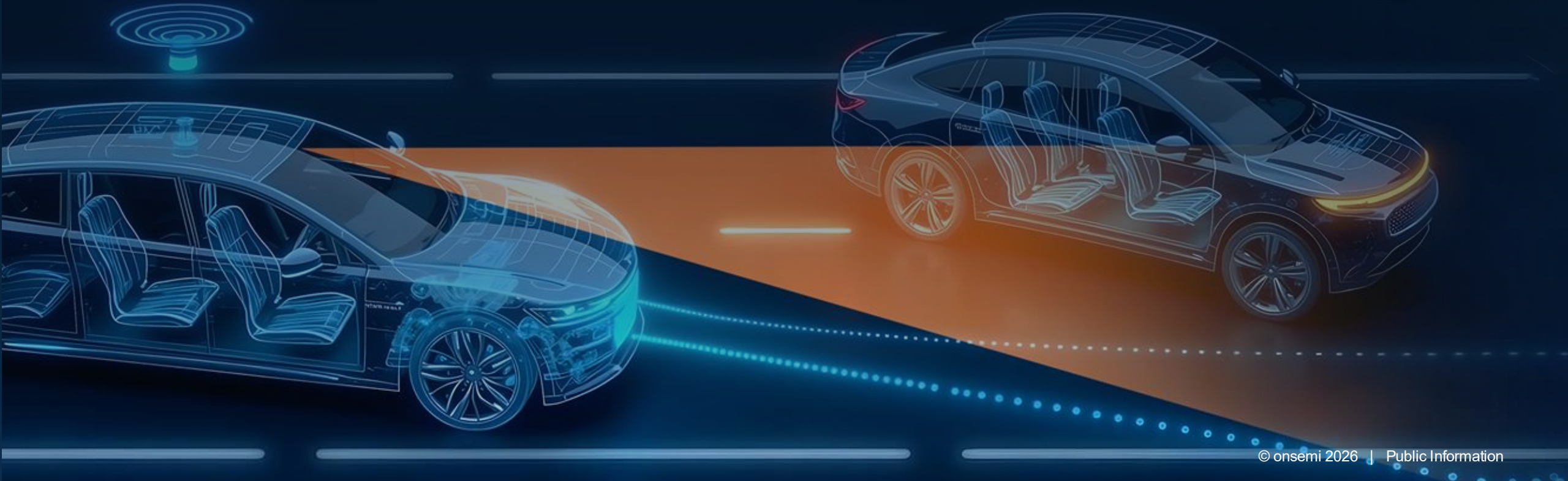
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Intelligent Sensing Growth Plan

Capitalize on Sensor Proliferation

Extend Sensing Performance Leadership with Treo

Enhance Vision with New Image Sensing Modalities



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Broadest Range of Sensing Solutions

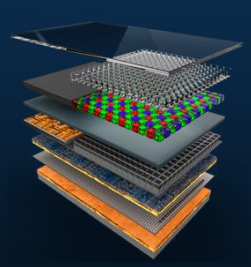
AUTONOMOUS

$15B TAM









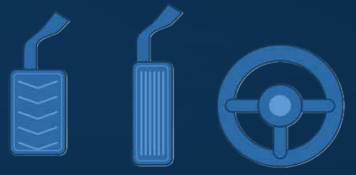
Image







Ultrasonic





Inductive

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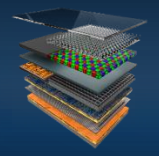
Sensors Proliferate As Autonomy Scales



2030

3x

Image Sensors



L2 → L4

1.5x

Ultrasonic Sensors



More use cases

1.5x

Inductive Sensors



x-by-wire extends

2026

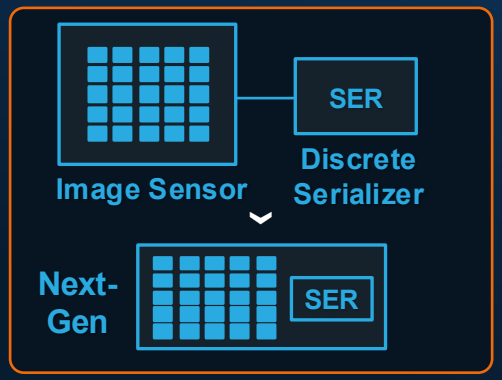
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Raising the Bar on Intelligent Sensing

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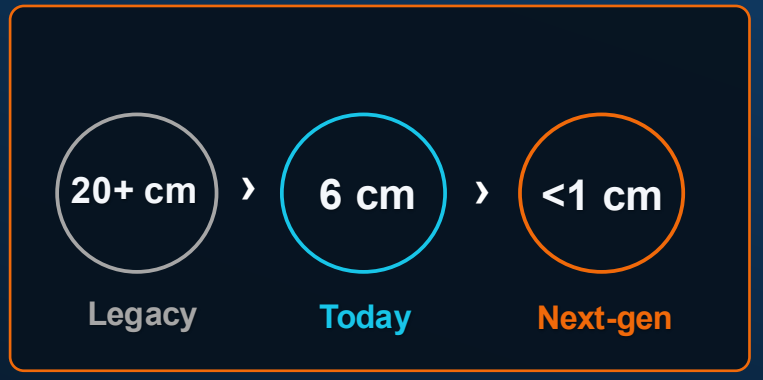


Image Sensing



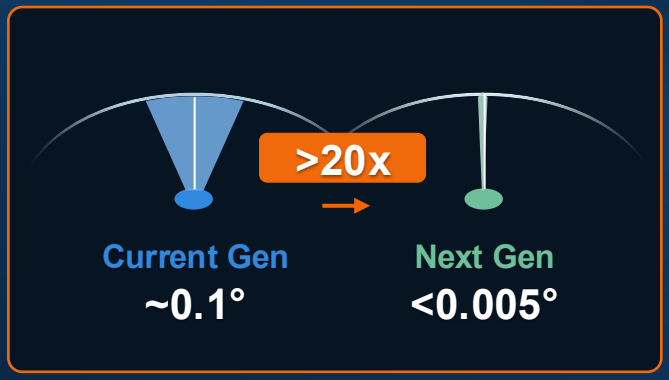
Available 2027

Ultrasonic Sensing



Available 2027

Inductive Sensing



Available 2027

Enabled by Treo

10%
BOM Savings

20x
Performance

Customer Value

Accuracy → Safety & Reliability

Integration → System Cost

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Enhancing Vision for the Next Phase of Perception



PERCEPTION STACK	CHALLENGES
Vision	Adverse weather conditions
Radar	Spatial resolution
Lidar	System cost

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Enhancing Vision for the Next Phase of Perception

onsemi

Superhuman Vision



SWIR See through fog and rain

Industrial available today, Auto in Advanced R&D



iToF High-res depth at <15M
Detect hazard at 100M

Industrial available today, Auto in Proof-of-concept



Vision Capture detail in any light

HDR available today



Customer Value

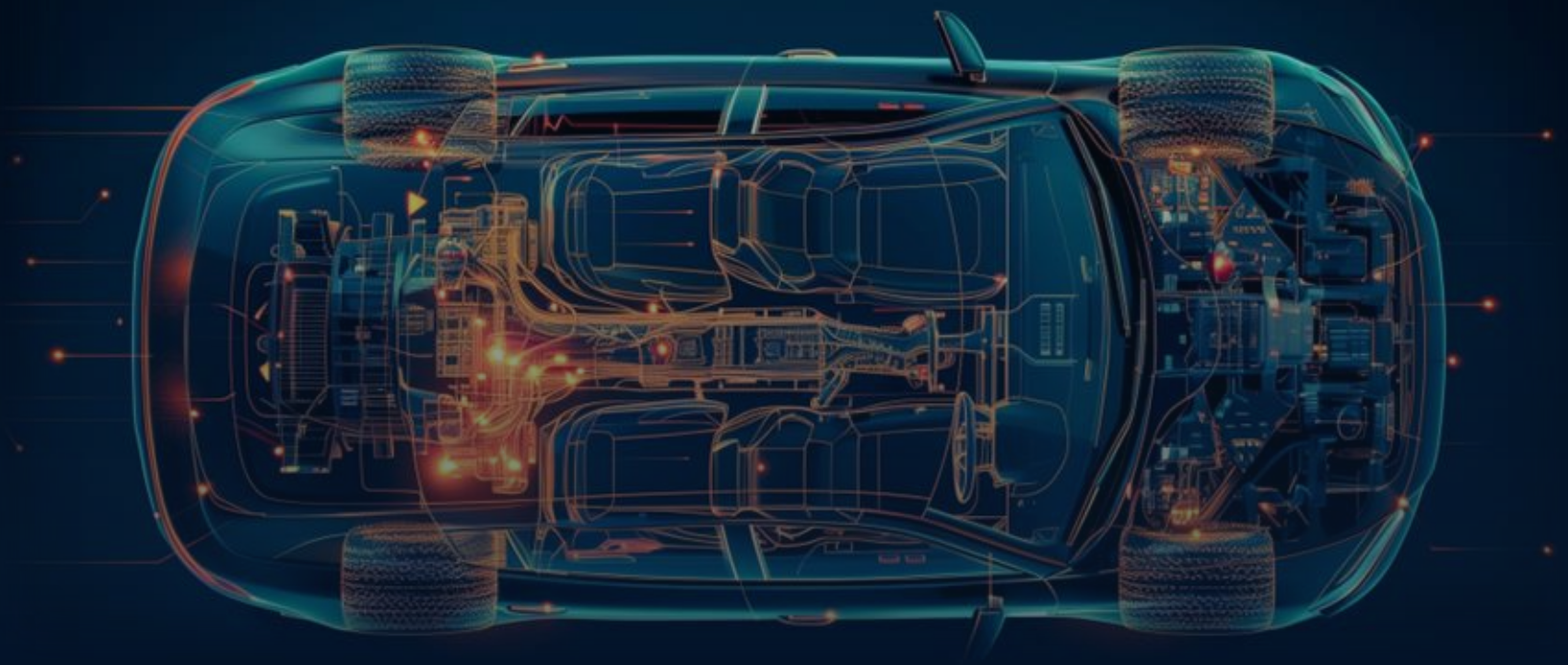
Enhanced Vision → Safety

iToF → System Cost

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New Growth Driver: Software Defined Vehicle/Zonal

Expand Content and Intelligence at the Nodes



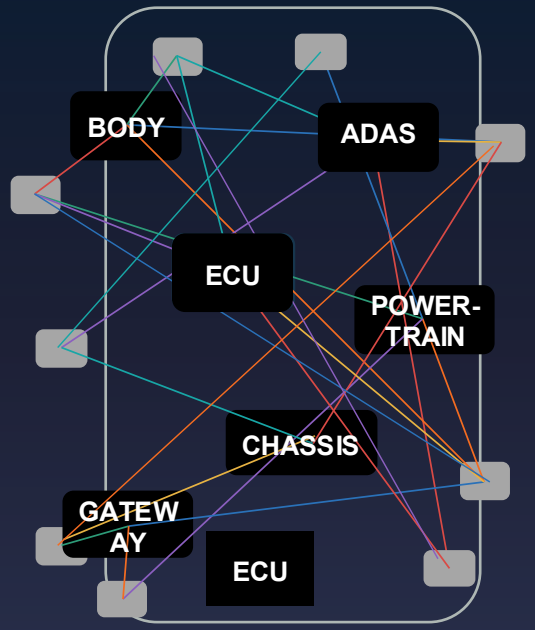
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New Growth Driver: SDV/Zonal

SDV/ZONAL
$9B TAM



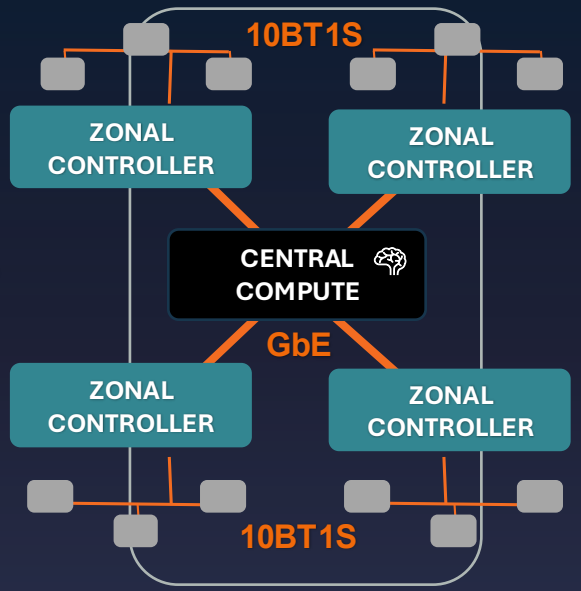
Domain-Based IVN (Today)



COMPLEX

ECU sprawl, SW in each node, mixed protocols

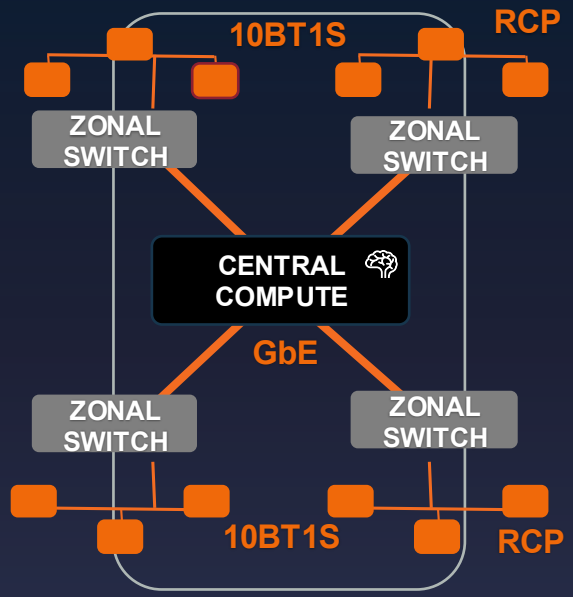
Zonal w/ 10BT1S



SIMPLIFIED

Ethernet to the edge, less cable complexity, costs

Zonal w/ onsemi RCP



OPTIMIZED FOR SDV SW

Only in central compute and intelligent nodes

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New Growth Driver: SDV/Zonal

SDV/ZONAL
$9B TAM



Basic Ethernet Node

CENTRAL COMPUTE

ZONAL CONTROLLER
$$$

Ultrasonic Node	LED Node
MCU w/ SW	MCU w/ SW
onsemi 10BT1S	onsemi 10BT1S
onsemi Ultrasonic	onsemi LED driver

Ethernet Node with RCP

CENTRAL COMPUTE

ZONAL SWITCH $

Ultrasonic Node	LED Node
onsemi 10BT1S RCP w/ SW	onsemi 10BT1S RCP w/ SW
onsemi Ultrasonic	onsemi LED driver

Treo Intelligent Node

CENTRAL COMPUTE

ZONAL SWITCH $

Ultrasonic Node	LED Node
onsemi 10BT1S RCP w/ SW Ultrasonic	onsemi 10BT1S RCP w/ SW LED

onsemi VALUE

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Leading the SDV Evolution

SDV/ZONAL
$9B TAM



Basic Ethernet Node

CENTRAL COMPUTE

ZONAL CONTROLLER
$$$

Ultrasonic Node | LED Node

In Production
$ Today

Ethernet Node with RCP

CENTRAL COMPUTE

ZONAL SWITCH $

Ultrasonic Node | LED Node

Design-in 2027
2x $ Today

Treo Intelligent Node

CENTRAL COMPUTE

ZONAL SWITCH $

Ultrasonic Node | LED Node

Next-gen in 2028
3x $ Today

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Building the Car: onsemi in Every Subsystem

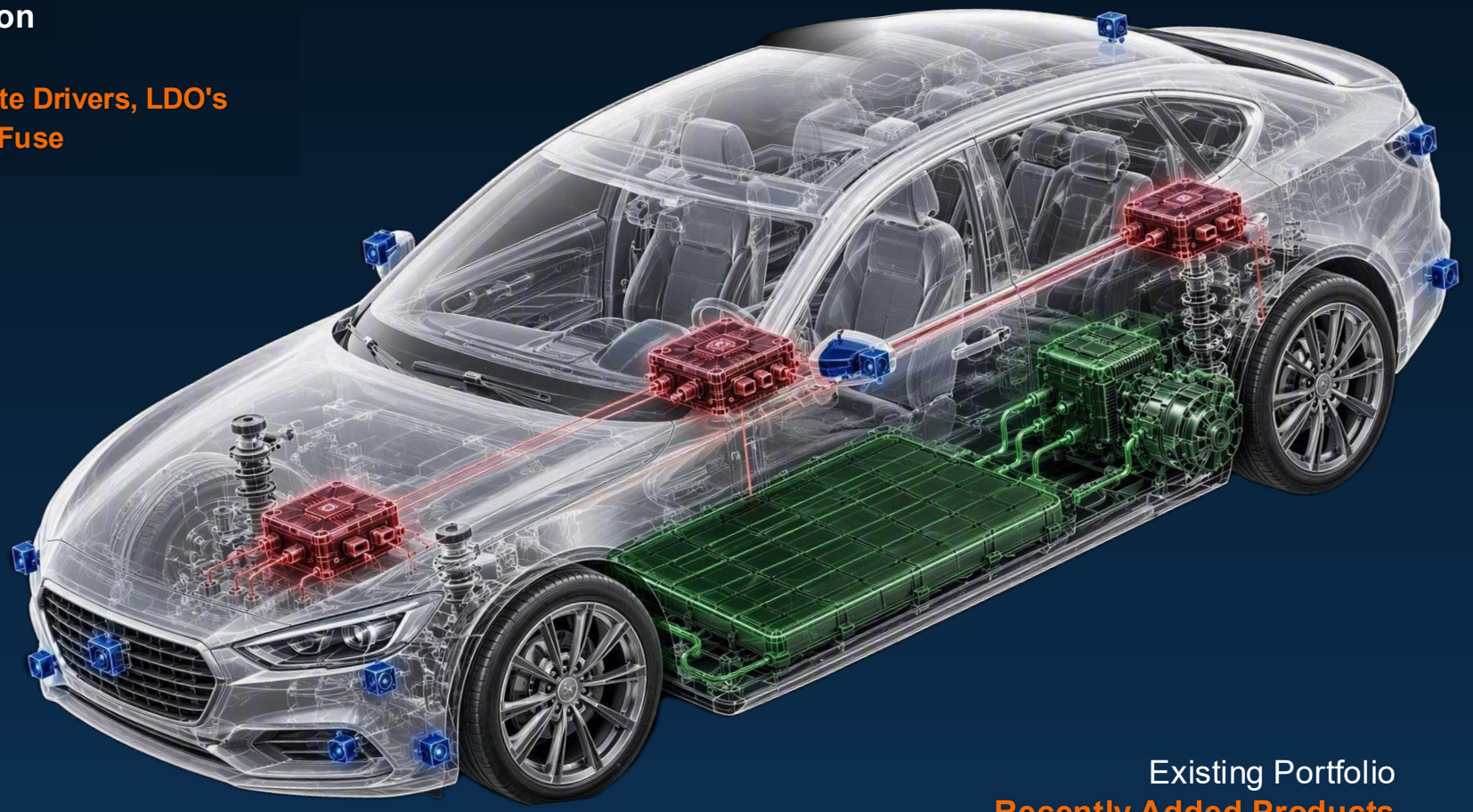
Vehicle Electrification xEV

HEV / PHEV / BEV
- EPP
- EliteSiC FET
- SiC Current Controller

48V Transition
- HV Si FET
- GaN/SiC Gate Drivers, LDO's
- SmartFET/eFuse

Zonal Electronics
- Auto LED Drivers
- SmartFET/eFuse
- 10BASE-T1S Ethernet
- CAN/LIN
- Standard Products (LDOs, Amps)
- Small Signal Protection

ADAS and Autonomous Driving Solutions
- 8Mp, 3Mp image sensor
- iToF
- SWIR
- Ultrasonic Sensing
- Inductive Sensing
- Rain & Light Sensing

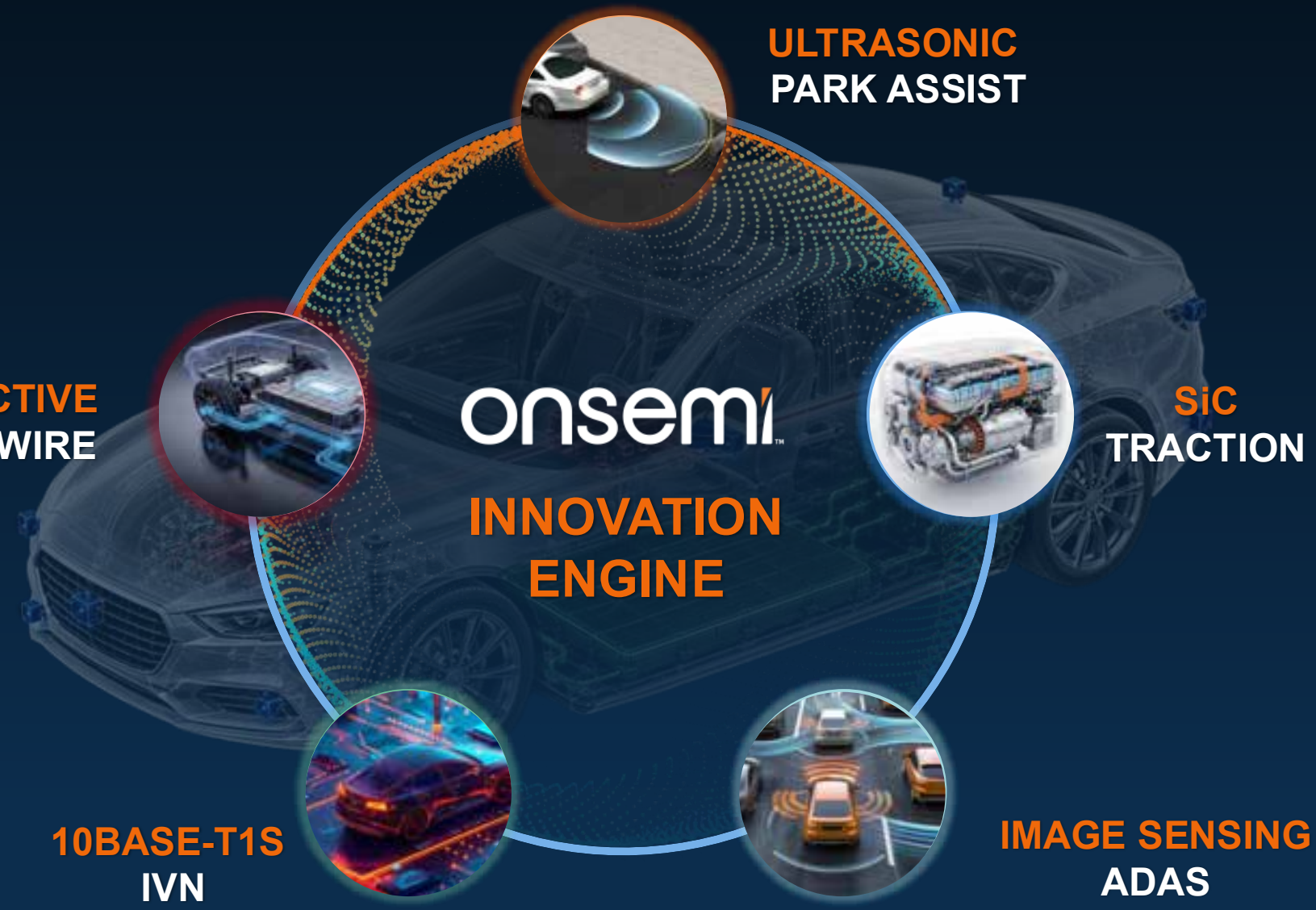


Existing Portfolio
Recently Added Products

Up to $2000 of onsemi content per vehicle

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Automotive Innovations…



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Automotive Innovations… Enable Growth in Industrial…

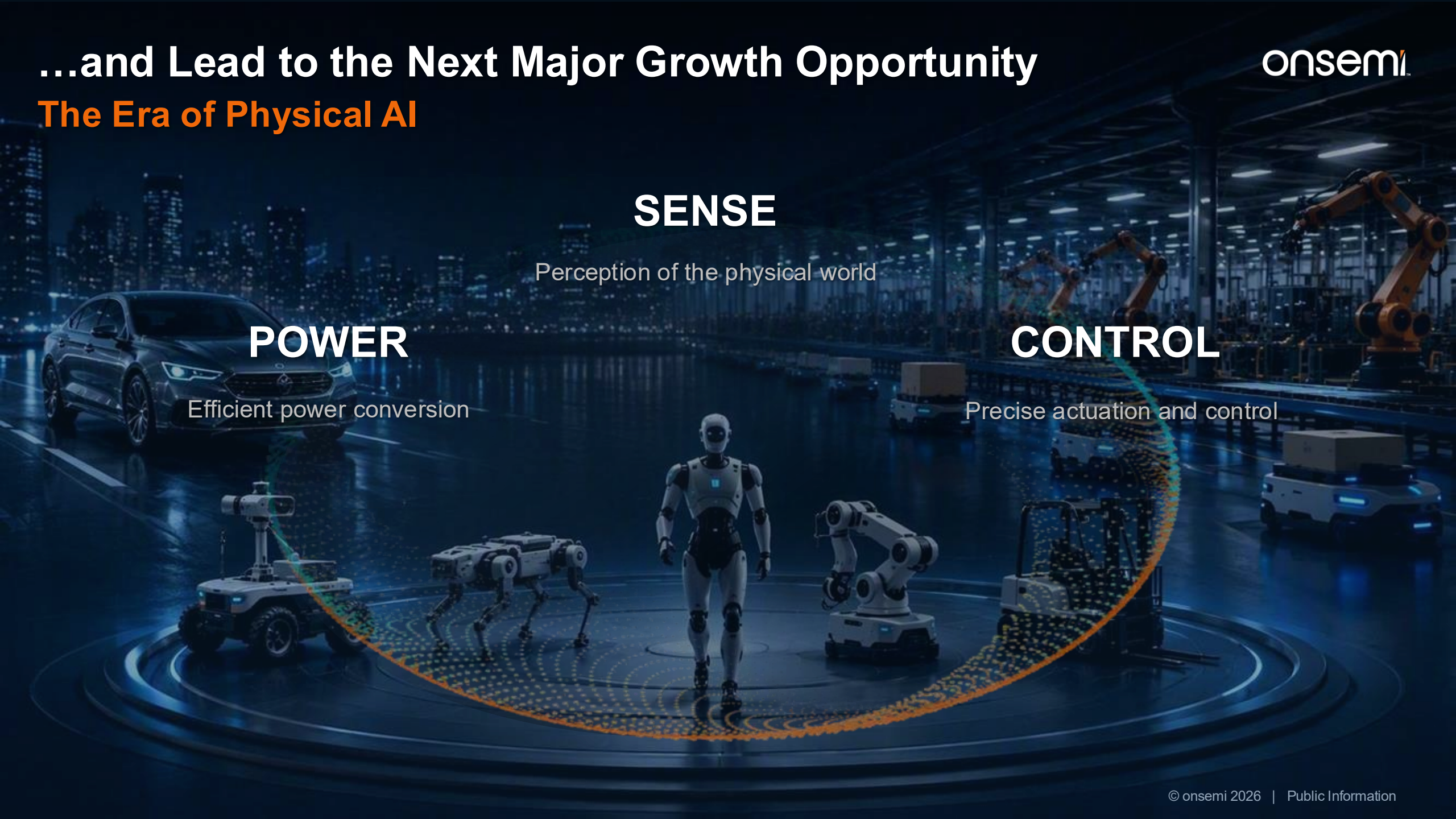
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…and Lead to the Next Major Growth Opportunity

The Era of Physical AI



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The Era of Physical AI has Already Begun

Autonomous machines that sense, decide, act and adapt



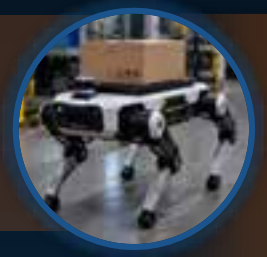
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The Evolution to Humanoids Yields Content Expansion



Warehouse AMRs

+ *Autonomy, Legs*



Legged AMR



Factory Arms

+ *Gripper Hands, Force Sensing*



Dexterous Hands



Autonomous Cars

+ *Multi-modal VLA, Reasoning*



"Reasoning" Vehicles

Physical AI:

$6B

TAM by 2030



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Building the Humanoid: onsemi in Every Subsystem

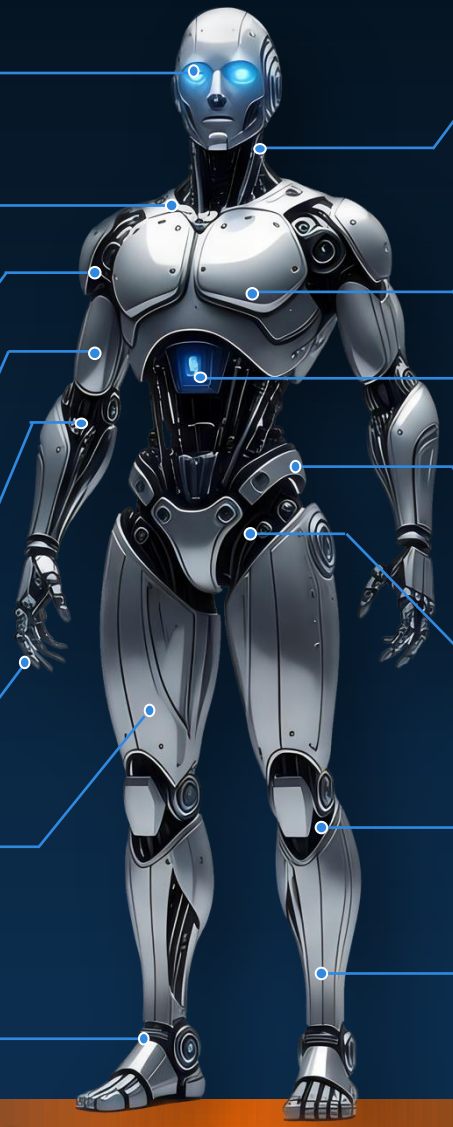
onsemi

Vision Systems
- Image sensors
- **iToF sensors**
- **SWIR**
- DC-DC/LDOs

30+ Limb Actuators
- **6x GaN FET**
- **3x GaN Driver**
- **Inductive sensors**
- **10BASE-T1S**
- **Intelligent Control**
- Current sensors
- UVP/OVP

15+ Hand Actuators
- MOSFET/**GaN**
- Gate Drivers
- **Intelligent Control**
- **10BASE-T1S**

HEAD/PERCEPTION
NECK
SHOULDERS
UPPER ARMS
ELBOWS
HANDS
LEGS
ANKLES/FEET



TORSO/COMPUTE
POWER SYSTEM
CORE SENSORS
WAIST/HIPS
BATTERY
KNEES
COMMUNICATION

Power Tree
- **eFuse**
- SiC/MOSFET
- DC-DC/LDOs

Sensors
- Ultrasonic sensors
- Pressure/force
- Audio DSP
- **Sensor Hub MCU**
- Temp monitor

Connectivity
- **10BASE-T1S**
- CAN/LIN
- BLE

Existing Portfolio
Recently Added Products

Up to $900 of onsemi content per humanoid

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Expanding the Core: Automotive and Industrial

2030

Today

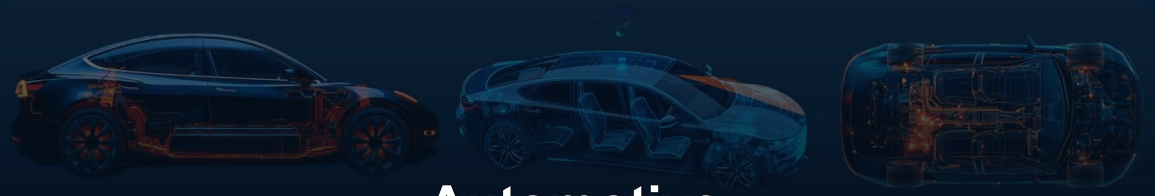
Value Drivers

9%
CAGR

EPP Disruption: System Play

Intelligent Sensing: Content Expansion

SDV/Zonal: New Growth Engine



Automotive

10%
CAGR

Leverage Auto: SAM Expansion

Physical AI: New Growth Engine

AI Halo: New Growth Engine



Industrial

Delivering Margin Expansion

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Turning Technology Leadership into Durable Financial Performance

Thad Trent

Executive Vice President and CFO

Market Inflection. Differentiated Capabilities. Shareholder Value Creation.



HIGH-VALUE, SECULAR MARKETS

AI Data Center, Automotive, Industrial

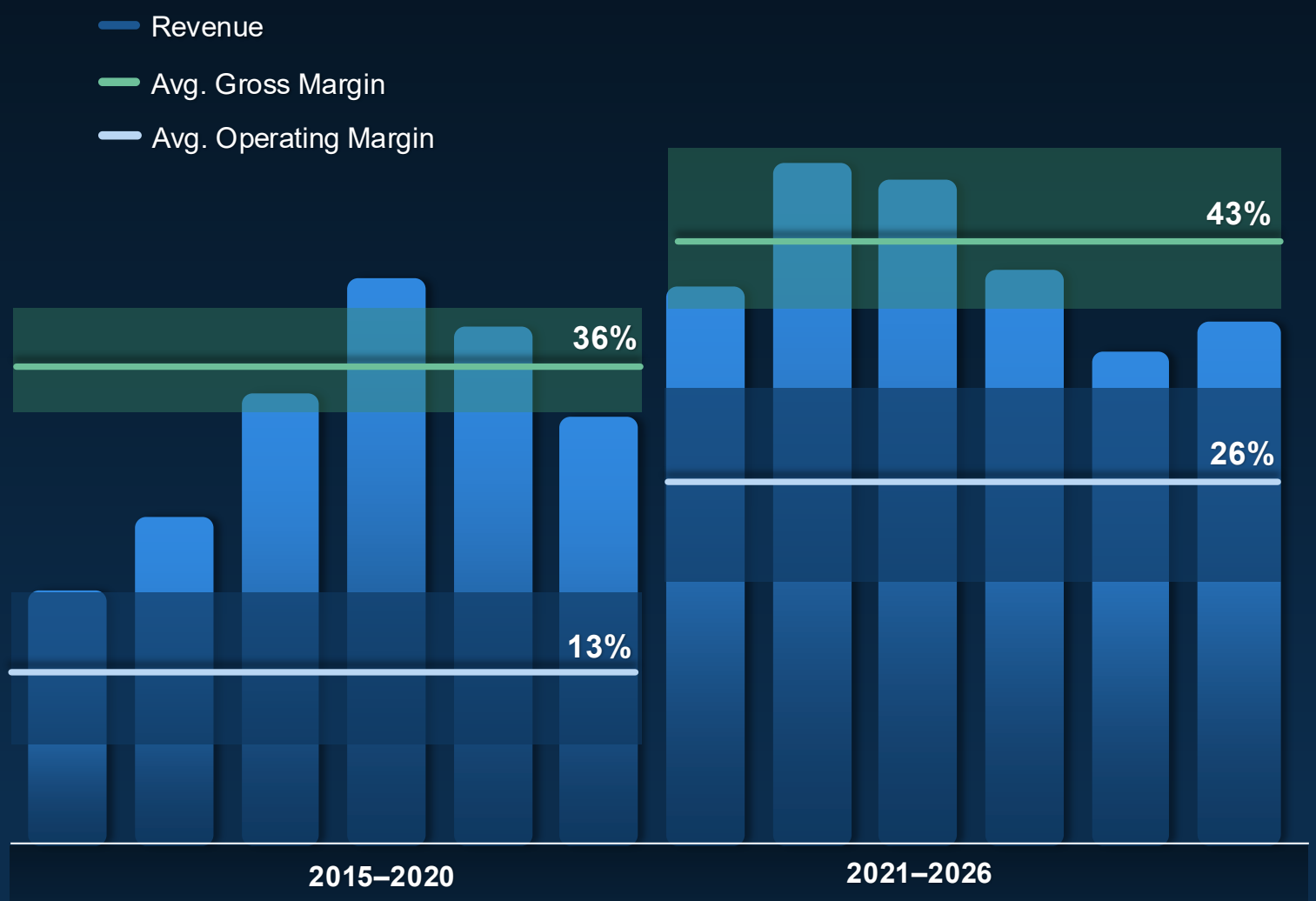
DIFFERENTIATED CAPABILITIES

Differentiated technology expands margins

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The Power of onsemi's Transformation

Non-GAAP



*BANDS REPRESENT HIGH AND LOW OF EACH METRIC DURING THAT PERIOD

Structural step function margin improvement

- Differentiated products, Fab Right, portfolio rationalization – completed exits of ~$900M annualized

Higher Operating leverage

- Improved cost structure, OpEx efficiency (Rev/employee increased ~2X)

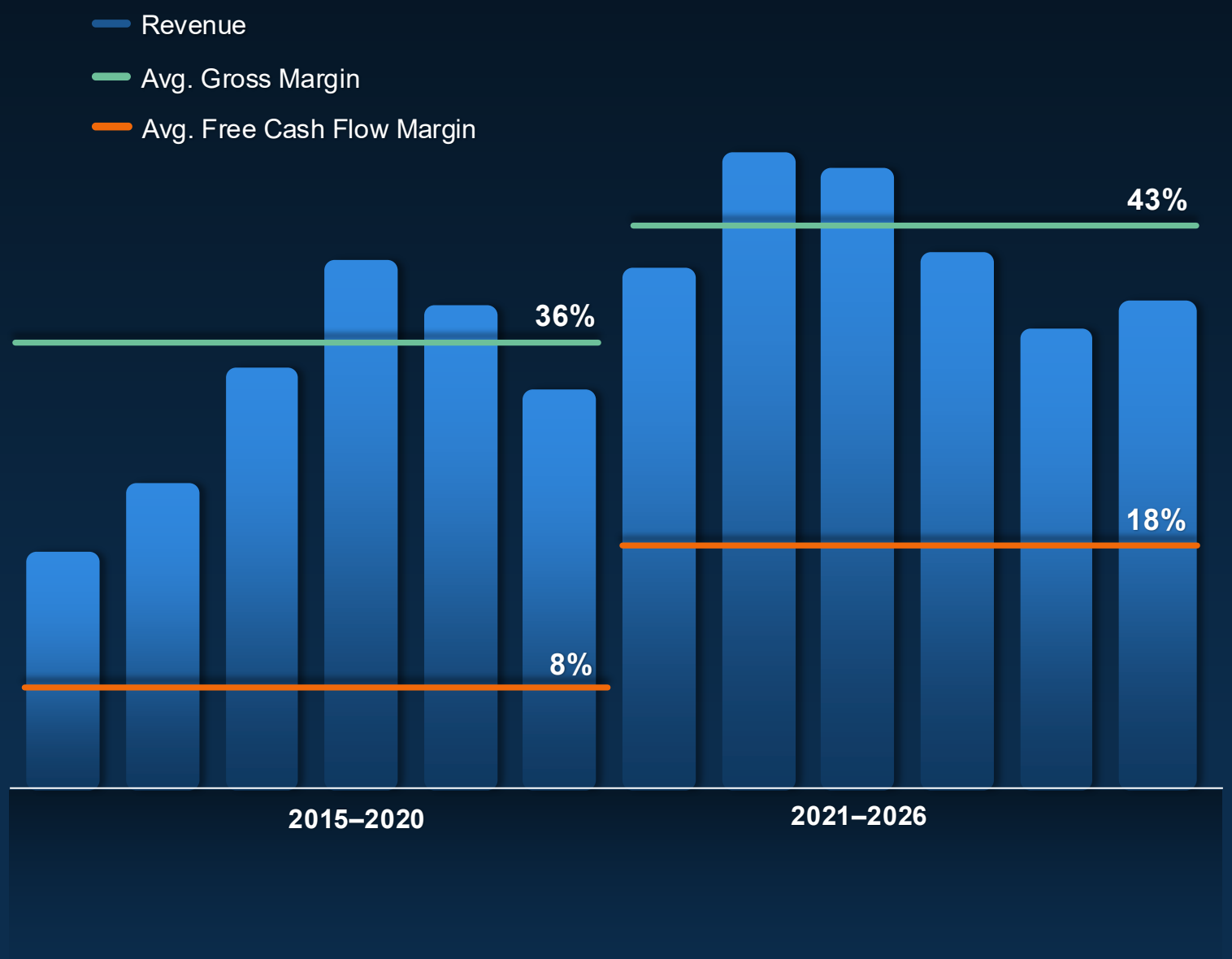
Proven downside resilience

- Sustainable and predictable results

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The Power of onsemi's Transformation

Non-GAAP



Structural step function margin improvement

- Differentiated products, Fab Right, portfolio rationalization – completed exits of ~$900M annualized

Higher Operating leverage

- Improved cost structure, OpEx efficiency (Rev/employee increased ~2X)

Proven downside resilience

- Sustainable and predictable results

Strong Free Cash Flow Generation

- Transform from Manufacturing Co. to a Product Co.
- Brownfield capacity expansion

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Strategic Investments Drive Significant TAM Expansion

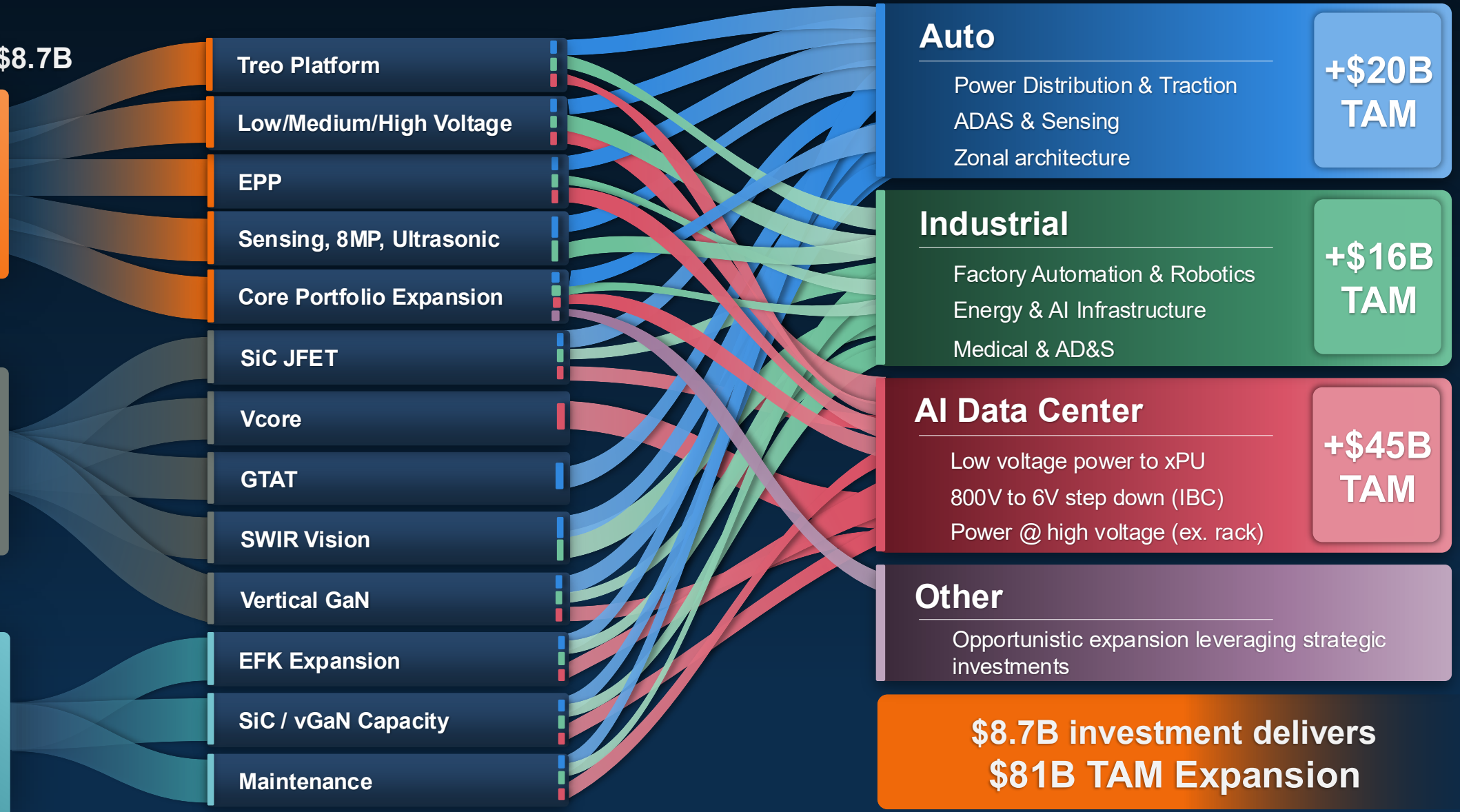
2021-2026

Total Investment: $8.7B

R&D
Organic Investments
$3.6B

M&A
Capability Expansion
$0.8B

CapEx
Capacity Expansion
$4.3B



$8.7B investment delivers $81B TAM Expansion

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Enabling Innovation Across a Global Customer Base

onsemi

Highly diversified customer footprint spanning 9,000+ customers globally



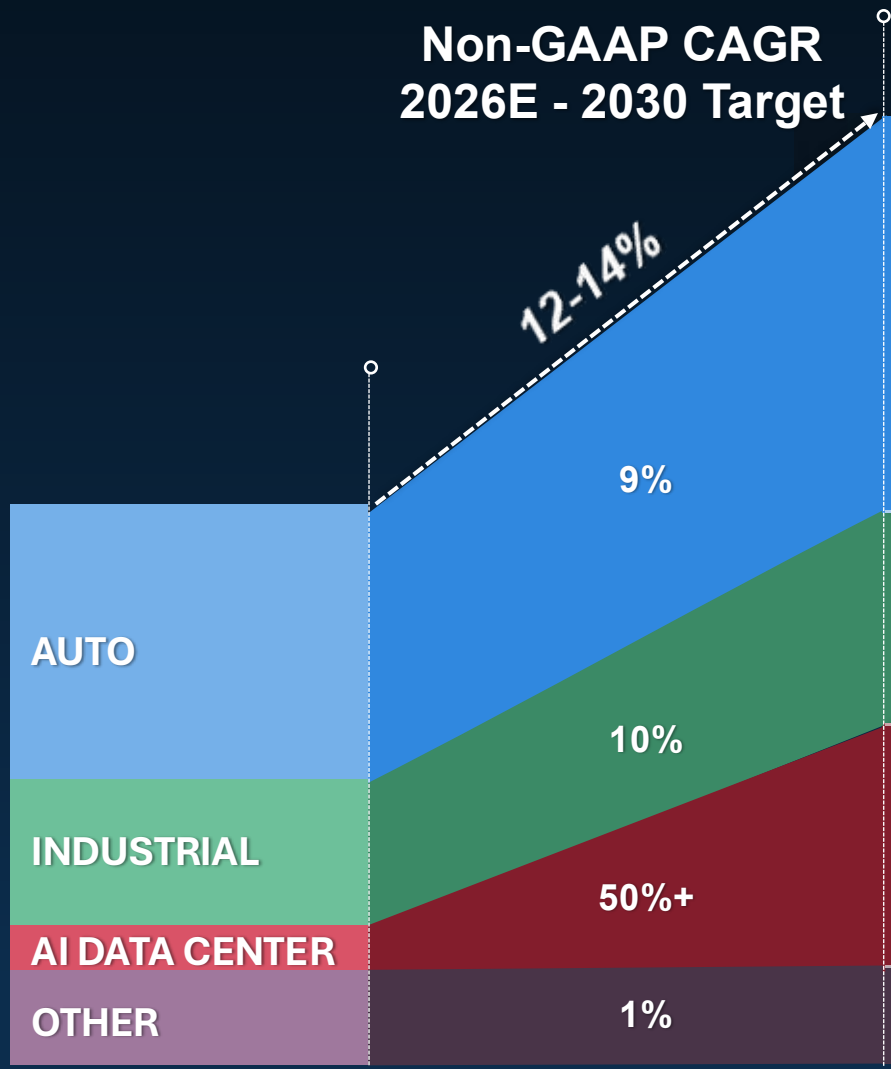




Deep strategic engagements addressing customers' most complex engineering challenges
Broad global distribution network to serve the mass market
Top 20 customers represent ~35% of revenue, no 10% customer

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Innovation and Portfolio Breadth Accelerates Growth





Auto

Drivers: electrification, Software-Defined Vehicles/Zonal, ADAS

~$2,000 content per vehicle

Outgrowing SAAR by high single digits



Industrial

Drivers: AI Halo, energy infrastructure, automation, medical, AD&S

Physical AI: $6B TAM by 2030; ~$900 content per humanoid



AI Data Center

Drivers: 800VDC, HV revenue acceleration, Vcore penetration

~$15K → ~$115K content per rack

Revenue > 5x in 2030 to > $2.5B



Other

Communications, Computing, Consumer

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Fab Right: Building a More Efficient, Scalable Manufacturing Network

2019 Footprint:

Fab-Liter



More efficient capacity drives gross margin expansion

Right sized, ready to scale on demand

Minimal CapEx needed to scale (5% of revenue)

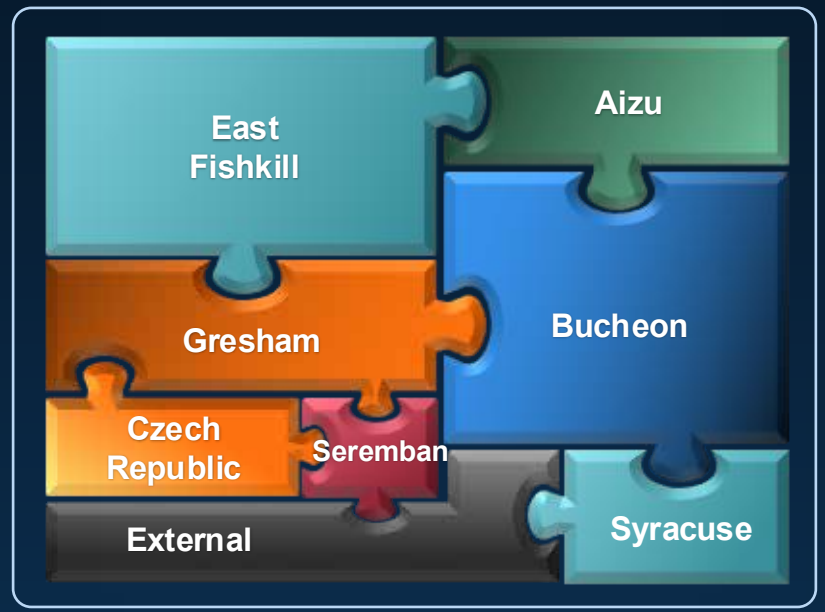
Exited five subscale fabs while expanding 300mm (EFK) capacity

Current footprint ~17% lower cost (at full utilization)

Additional Fab Right activities to drive further gross margin expansion

Current Footprint:

Fab Right

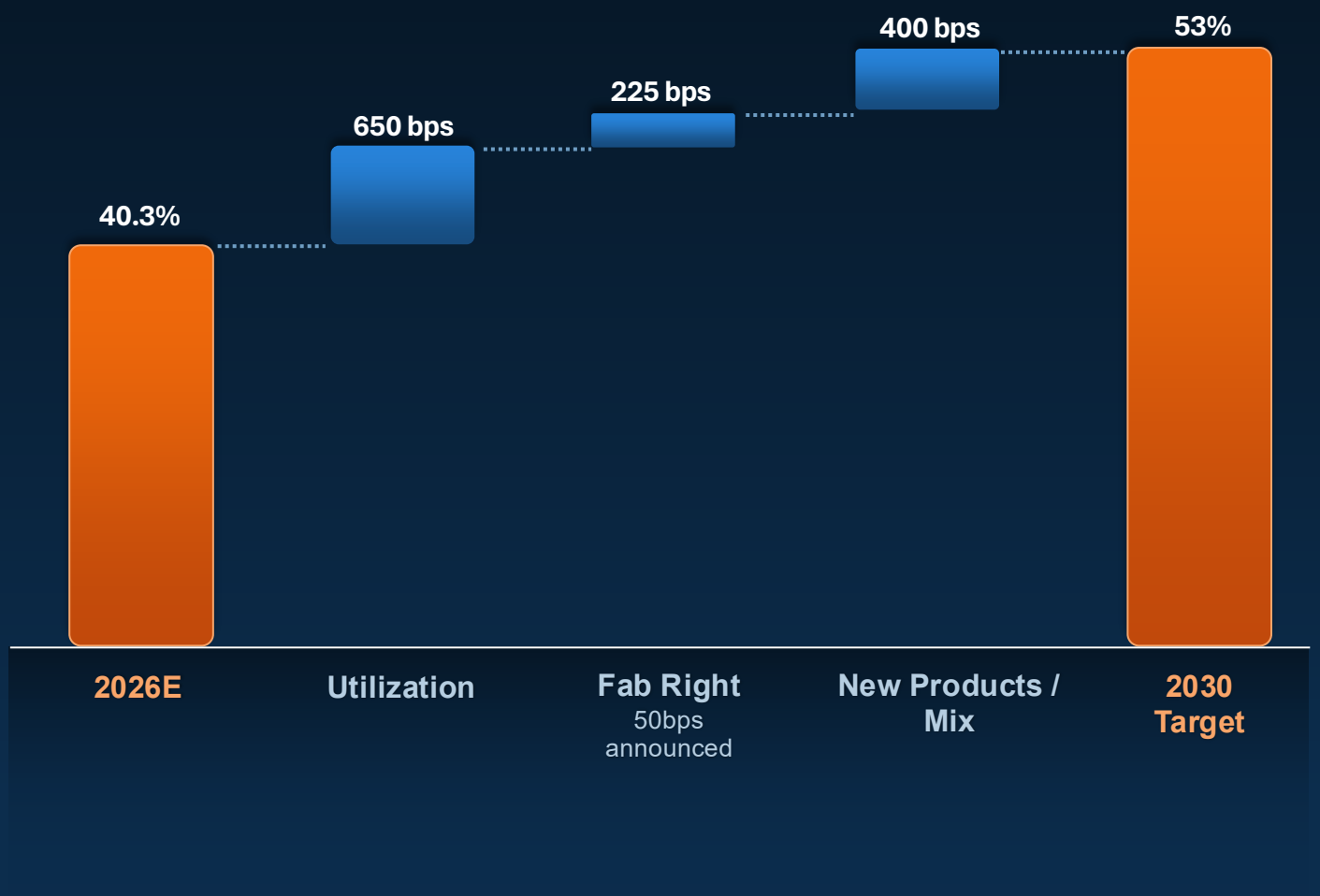


Scalable, Efficient, Lower Cost

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Growth and Innovation Drive Gross Margin Expansion

Non-GAAP



Utilization
- Volume driven ramp to full utilization
- Absorption of fixed costs

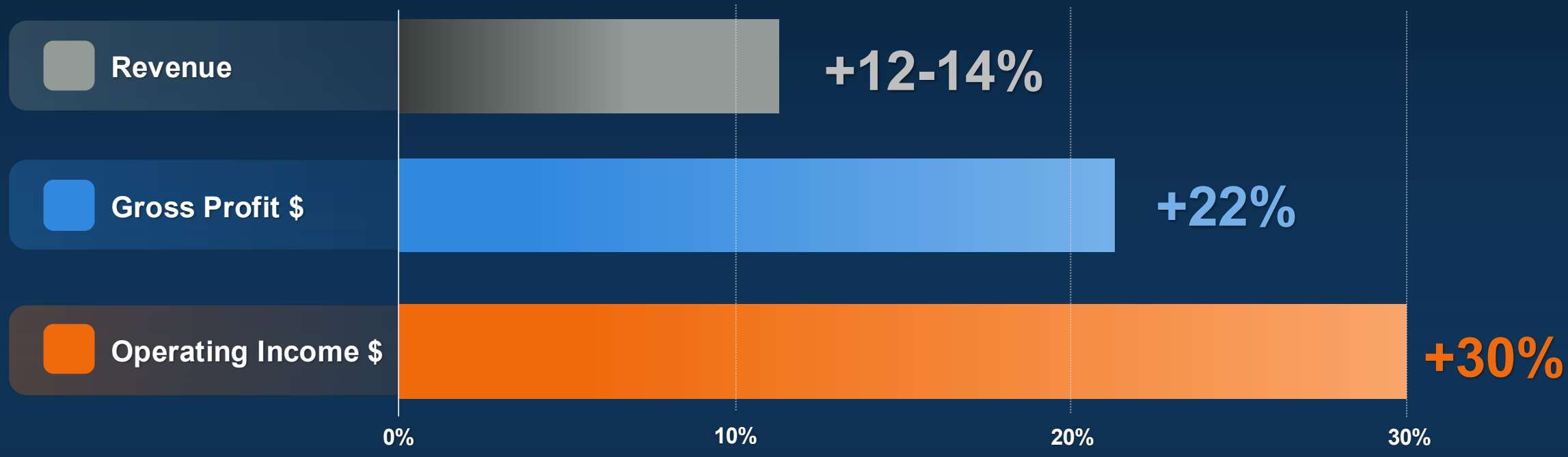
Fab Right
- Additional efficiency and cost optimization
- Capacity allocated to high value products
- Two site divestitures recently announced

New Products/ Mix
- Ramping differentiated products at accretive margins (Treo, EPP, vGaN)
- Portfolio mix shift in silicon power products
- Ramping high growth AI Data Center revenue

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Top-line Growth → Outsized Earnings Growth

Structural changes, innovation and execution deliver significant operating leverage



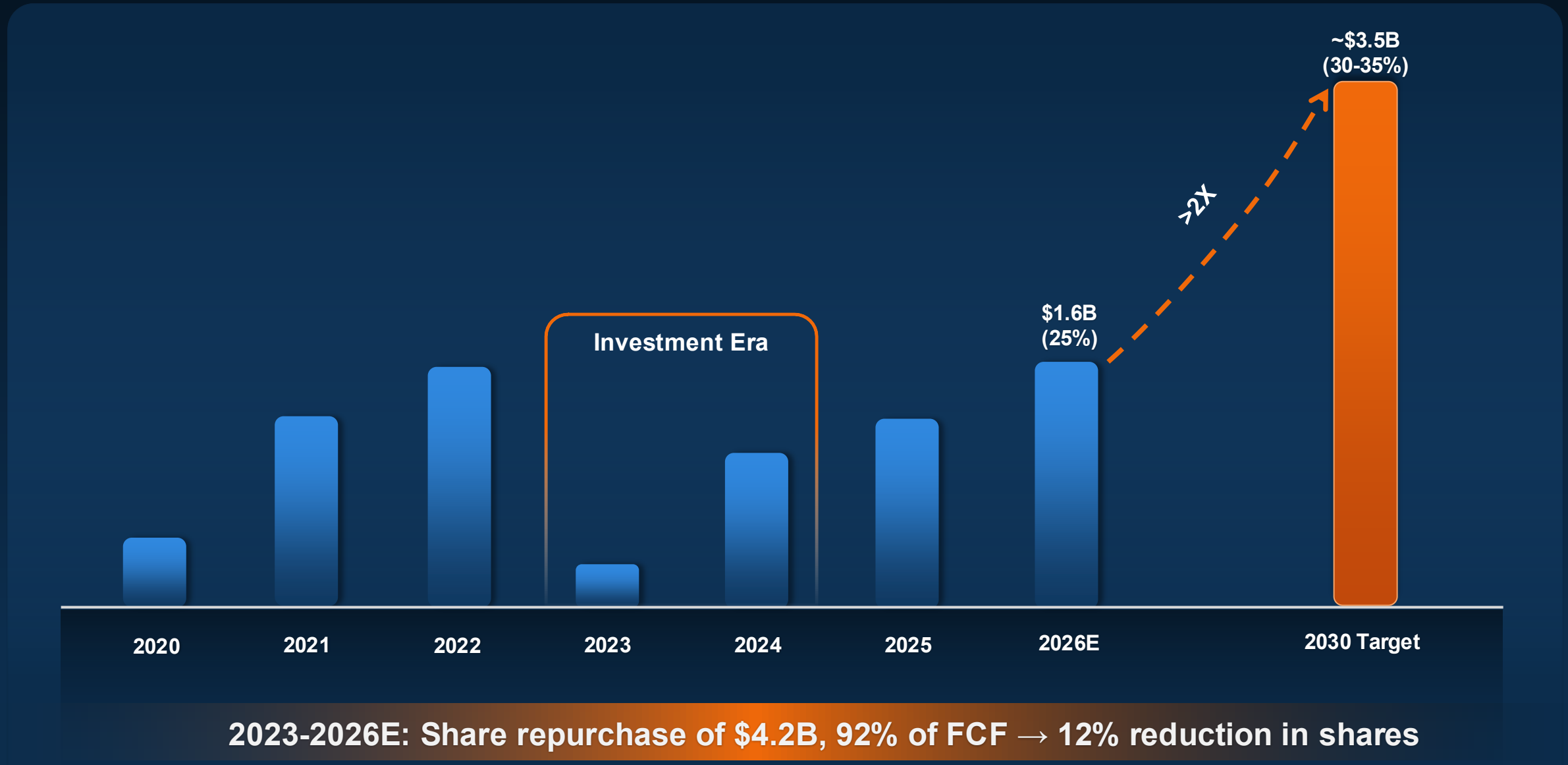
Non-GAAP CAGR, 2026E – 2030 Target

Gross profit grows 1.6x faster than revenue; operating income more than 2x faster.

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Free cash flow more than doubling by 2030

Monetizing Investments through scale and efficiency



2023-2026E: Share repurchase of $4.2B, 92% of FCF → 12% reduction in shares

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Disciplined Capital Allocation Compounds Shareholder Value

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REINVEST

Fund the highest-return growth

Differentiated products, R&D and capacity investments that strengthen competitive advantage.



STRATEGIC M&A

Expand the portfolio selectively

Add capabilities to expand TAM and accelerate time to market. Clear strategic and financial merit enhancing the financial model.



BALANCE SHEET

Preserve resilience and flexibility

Maintain strong liquidity and leverage profile.



RETURN CASH

Repurchase shares consistently

Return 100% of free cash flow through share repurchases. $5.3B remaining under the existing authorization.

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Technology Leadership Powers Shareholder Value

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Non-GAAP	2025A	2026E	2030 TARGET	
Revenue	**$6.0B**	**$6.5B**	**+12-14% CAGR**	Growth driven by highly differentiated products in fast growing markets
Gross Margin	**38.4%**	**40.3%**	**53%**	Utilization, high-value new products, and Fab Right
Operating Expenses	**19.8%**	**18.5%**	**15%**	Targeted R&D investment to expand capabilities and TAM
Operating Margin	**18.6%**	**21.9%**	**38%**	Operating income grows >2x revenue growth
CapEx	**5.7%**	**2.7%**	**~5%**	CapEx-light model for optimal capital allocation
Free Cash Flow	**23.7%**	**24.8%**	**30-35%**	Monetizing investments through scale and efficiency

Non-GAAP tax rate remains at 15% through 2030

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Synaptics Accelerates Financial Model

Non-GAAP	Synaptics Standalone Post-Synergies	
Revenue	**>15%**	Leverage **onsemi** sales channel to broaden customer base, increase content per platform, and for cross selling. Increases TAM by $30B
Gross Margin	**>55%**	Connected-compute capabilities at accretive gross margins
Operating Margin	**>30%**	**Accretive to EPS within ~18 months with $200M of synergies**

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Technology Leadership Powers Shareholder Value

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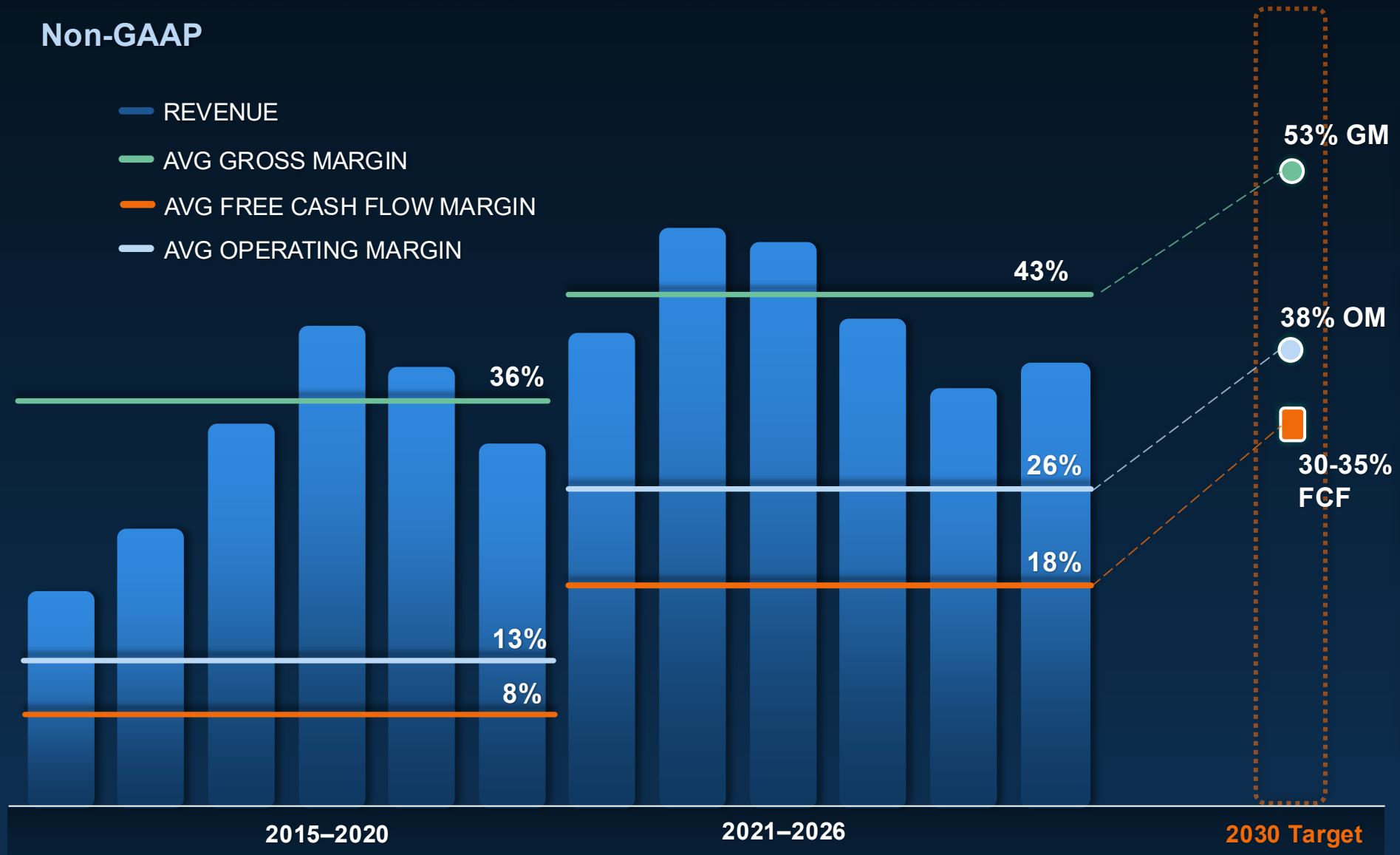
Non-GAAP	2025A	2026E	2030 TARGET	
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Non-GAAP tax rate remains at 15% through 2030

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The Power of onsemi's Transformation

Non-GAAP



- Accelerated growth, differentiated portfolio investments and Fab Right for gross margin expansion
- Streamlined manufacturing structure and OpEx efficiency drive significant operating leverage
- Leveraging past investments and capacity expansion support strong cash conversion
- **Target operating margin is greater than legacy gross margins**

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Market Inflection. Differentiated Capabilities. Shareholder Value Creation.



HIGH-VALUE, SECULAR MARKETS

AI data center, automotive, industrial

AI Data Center

Higher compute power driving a shift to high-voltage architectures and greater **onsemi** content.

Automotive

Electrification, autonomy and SDV/zonal architectures sustain content growth above SAAR.

Industrial

AI Halo driving power semi demand; physical AI emerging as a new **onsemi** growth vector.

DIFFERENTIATED CAPABILITIES

Differentiated technology expands margins

Unmatched breadth

A full LV and HV portfolio across silicon, SiC, GaN and vGaN.

Advanced platforms, exclusive to onsemi

Treo and EPP create differentiated power systems with best-in-class performance.

Scaled investment

$8.7B invested over five years expands the addressable market by $81B.

COMPOUNDING FINANCIALS

Non-GAAP · 2026E → 2030 Target

+12–14%	Revenue CAGR
53%	Gross margin expansion
38%	Operating margin expansion increases >2× revenue
30–35%	Free cash flow margin expansion to ~$3.5B

Expanding markets + differentiated capabilities + disciplined execution = durable, profitable growth

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APPENDIX

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Appendix – GAAP to Non-GAAP Reconciliation

Reconciliation of GAAP to Non-GAAP Gross Margin						
Fiscal Year	**FY 2015**	**FY 2016**	**FY 2017**	**FY 2018**	**FY 2019**	**FY 2020**
GAAP Gross Margin	34.1%	33.2%	36.7%	38.1%	35.8%	32.7%
a) Amortization of fair market value step-up of inventory	0.0%	1.7%	0.2%	0.0%	0.4%	0.0%
b) Actuarial (gains)/losses on pension plans	0.0%	0.1%	0.0%	0.0%	0.0%	0.0%
c) Sell-through / sell-in adjustment	0.0%	0.0%	0.1%	0.0%	0.0%	0.0%
Non-GAAP Gross Margin	34.1%	35.0%	37.0%	38.1%	36.1%	32.7%

Fiscal Year	**FY 2021**	**FY 2022**	**FY 2023**	**FY 2024**	**FY 2025**
GAAP Gross Margin	40.3%	49.0%	47.1%	45.4%	33.1%
a) Impact of business wind down	0.0%	0.2%	0.0%	0.0%	0.0%
b) Amortization of acquisition-related intangible assets	0.0%	0.1%	0.1%	0.1%	0.1%
c) Non-recurring facility costs	0.1%	0.0%	0.0%	0.0%	0.0%
d) Restructuring-related inventory and other charges	0.0%	0.0%	0.0%	0.0%	5.2%
Non-GAAP Gross Margin	40.4%	49.2%	47.1%	45.5%	38.4%

Certain amounts in the above tables may not total due to rounding of individual amounts.

Appendix – GAAP to Non-GAAP Reconciliation

onsemi

Reconciliation of GAAP to Non-GAAP Operating Margin						
Fiscal Year	**FY 2015**	**FY 2016**	**FY 2017**	**FY 2018**	**FY 2019**	**FY 2020**
GAAP Operating Margin	7.5%	6.0%	12.3%	14.4%	7.8%	6.6%
a) Amortization of acquisition-related intangible assets	3.9%	2.7%	2.2%	1.9%	2.1%	2.3%
b) Restructuring, asset impairments and other, net	0.3%	0.8%	0.4%	0.1%	0.5%	1.2%
c) Goodwill and intangible asset impairment	0.1%	0.1%	0.2%	0.1%	0.0%	0.0%
d) Third party acquisition and divestiture-related costs	0.1%	0.7%	0.1%	0.1%	0.2%	0.0%
e) Amortization of fair market value step-up of inventory	0.0%	1.7%	0.2%	0.0%	0.4%	0.0%
f) Litigation settlement	0.0%	0.0%	0.0%	0.0%	3.1%	0.0%
g) Actuarial (gains)/losses on pension plans	-0.1%	0.3%	0.0%	0.0%	0.0%	0.0%
h) Sell-through / sell-in adjustment	0.0%	0.0%	-0.7%	0.0%	0.0%	0.0%
i) R&D costs related to licensing income	0.0%	0.0%	0.2%	0.1%	0.0%	0.0%
Non-GAAP Operating Margin	11.7%	12.3%	15.0%	16.7%	14.1%	10.2%

Fiscal Year	**FY 2021**	**FY 2022**	**FY 2023**	**FY 2024**	**FY 2025**
GAAP Operating Margin	19.1%	28.3%	30.8%	25.0%	1.4%
a) Amortization of acquisition-related intangible assets	1.5%	1.0%	0.7%	0.8%	0.8%
b) Restructuring, asset impairments and other, net	1.1%	0.2%	0.9%	1.9%	11.1%
c) Goodwill and intangible asset impairment	0.0%	4.6%	0.0%	0.0%	0.0%
d) Third party acquisition and divestiture-related costs	0.2%	0.2%	0.0%	0.2%	0.1%
e) Non-recurring facility costs	0.1%	0.0%	0.0%	0.0%	0.0%
f) Impact of business wind down	0.0%	0.2%	0.0%	0.0%	0.0%
g) Restructuring-related inventory and other charges	0.0%	0.0%	0.0%	0.0%	5.2%
Non-GAAP Operating Margin	21.9%	34.5%	32.3%	27.9%	18.6%

Certain amounts in the above tables may not total due to rounding of individual amounts.

Appendix – GAAP to Non-GAAP Reconciliation

(in millions, except percentages)

Reconciliation of GAAP to Non-GAAP Operating Expenses	FY 2015	FY 2016	FY 2017	FY 2018	FY 2019	FY 2020
GAAP Operating Expenses	$ 932.1	$ 1,060.8	$ 1,352.9	$ 1,391.5	$ 1,540.9	$ 1,367.1
a) Amortization of acquisition-related intangible assets	(135.7)	(104.8)	(123.8)	(111.7)	(115.2)	(120.3)
b) Restructuring, asset impairments and other, net	(9.3)	(33.2)	(20.8)	(4.3)	(28.7)	(65.2)
c) Goodwill & intangible asset impairment	(3.8)	(2.2)	(13.1)	(6.8)	(1.6)	(1.3)
d) Third-party acquisition/divestiture costs	(3.5)	(25.8)	(3.2)	(4.4)	(11.3)	(1.0)
e) Actuarial gains/(losses) pension	4.2	(6.8)	0.7	-	-	-
f) R&D costs related to licensing income	-	-	(10.0)	-	-	-
g) Litigation settlement	-	-	-	-	(169.5)	-
i) R&D costs related to licensing income	-	-	-	(7.0)	-	-
Non-GAAP Operating Expenses	$ 784.0	$ 888.0	$ 1,182.7	$ 1,257.3	$ 1,214.6	$ 1,179.3
Non-GAAP Operating Expense Margin	22.4%	22.7%	22.0%	21.4%	22.0%	22.4%

Reconciliation of GAAP to Non-GAAP Operating Income	FY 2015	FY 2016	FY 2017	FY 2018	FY 2019	FY 2020
GAAP Operating Income	$ 261.1	$ 236.1	$ 680.9	$ 847.2	$ 432.7	$ 348.7
a) Amortization of acquisition-related intangible assets	135.7	104.8	123.8	111.7	115.2	120.3
b) Restructuring, asset impairments and other, net	9.3	33.2	20.8	4.3	28.7	65.2
c) Goodwill & intangible asset impairment	3.8	2.2	13.1	6.8	1.6	1.3
d) Third-party acquisition/divestiture costs	3.5	25.8	3.2	4.4	11.3	1.0
g) Amortization of fair value inventory step-up	-	67.5	13.6	1.0	19.6	-
h) Actuarial gains/(losses) pension	(5.0)	10.0	1.9	-	-	-
i) Litigation settlement	-	-	-	-	169.5	-
l) sell-through to sell in adjustment	-	-	(59.0)	-	-	-
m) R&D costs related to licensing income	-	-	10.0	7.0	-	-
Non-GAAP Operating Income	$ 408.4	$ 479.6	$ 808.3	$ 982.4	$ 778.6	$ 536.5

Certain amounts in the above tables may not total due to rounding of individual amounts.

Appendix – GAAP to Non-GAAP Reconciliation

(in millions, except percentages)

Reconciliation of GAAP to Non-GAAP Operating Expenses	FY 2021	FY 2022	FY 2023	FY 2024	FY 2025
GAAP Operating Expenses	$ 1,426.7	$ 1,717.2	$ 1,344.8	$ 1,448.4	$ 1,899.7
a) Amortization of acquisition-related intangible assets	(99.0)	(81.2)	(51.1)	(52.0)	(44.4)
b) Restructuring, asset impairments and other, net	(71.4)	(17.9)	(74.9)	(133.9)	(666.9)
c) Goodwill & intangible asset impairment	(2.9)	(386.8)	-	-	-
d) Third-party acquisition/divestiture costs	(11.9)	(12.9)	1.3	(14.0)	(4.3)
e) Impact of business wind down	-	6.8	-	-	-
f) Adjustments to contingent consideration	-	-	-	-	1.3
Non-GAAP Operating Expenses	$ 1,241.5	$ 1,225.2	$ 1,220.1	$ 1,248.5	$ 1,185.4
Non-GAAP Operating Expense Margin	18.4%	14.7%	14.8%	17.6%	19.8%

Reconciliation of GAAP to Non-GAAP Operating Income	FY 2021	FY 2022	FY 2023	FY 2024	FY 2025
GAAP Operating Income	$ 1,287.6	$ 2,360.0	$ 2,538.7	$ 1,767.7	$ 84.2
a) Amortization of acquisition-related intangible assets	99.0	82.8	56.8	58.3	49.4
b) Restructuring, asset impairments and other, net	71.4	17.9	74.9	133.9	666.9
c) Goodwill & intangible asset impairment	2.9	386.8	-	-	-
d) Third-party acquisition/divestiture costs	11.9	12.9	(1.3)	14.0	4.3
e) Non-recurring facility costs	5.5	-	-	-	-
f) Impact of business wind down	-	12.7	(3.9)	-	-
g) Amortization of fair value inventory step-up	-	-	-	-	2.4
h) Restructuring-related inventory charges	-	-	-	-	313.6
o) Adjustments to contingent consideration	-	-	-	-	(1.3)
Non-GAAP Operating Income	$ 1,478.3	$ 2,873.1	$ 2,665.2	$ 1,973.9	$ 1,119.5

Certain amounts in the above tables may not total due to rounding of individual amounts.

Appendix – GAAP to Non-GAAP Reconciliation

(in millions, except percentages)

Reconciliation of net cash provided by operating activities to free cash flow						
Fiscal Year	FY 2015	FY 2016	FY 2017	FY 2018	FY 2019	FY 2020
Net cash provided by operating activities	$ 470.6	$ 581.2	$ 1,094.2	$ 1,274.2	$ 694.7	$ 884.3
Purchase of property, plant & equipment	$ (272.2)	$ (108.9)	$ (395.7)	$ (514.8)	$ (534.6)	$ (383.6)
Free Cash Flow	$ 198.4	$ 472.3	$ 698.5	$ 759.4	$ 160.1	$ 500.7
Free Cash Flow Margin	5.7%	12.1%	13.0%	13.0%	2.9%	9.5%

Reconciliation of net cash provided by operating activities to free cash flow	FY 2021	FY 2022	FY 2023	FY 2024	FY 2025
Net cash provided by operating activities	$ 1,782.0	$ 2,633.1	$ 1,977.5	$ 1,906.4	$ 1,759.8
Purchase of property, plant & equipment	$ (444.6)	$ (1,005.0)	$ (1,575.6)	$ (694.0)	$ (341.2)
Free Cash Flow	$ 1,337.4	$ 1,628.1	$ 401.9	$ 1,212.4	$ 1,418.6
Free Cash Flow Margin	19.8%	19.6%	4.9%	17.1%	23.7%

Certain amounts in the above tables may not total due to rounding of individual amounts.

Notes and Sources

Charting a Path to Power the Next Decade of Innovation
Hassane El-Khoury, President and CEO

$5.3B remaining under the existing authorization.
- As reported through Q2’2026

2026 estimates are based on consensus

Notes and Sources

onsemi: Powering the AI Revolution
Achyut Shah, Group President, Power Solutions Group

GPU Rack Power (kW per Rack) vs Deployment Horizon Graph
- McKinsey & Company – *The shift to 800-volt DC at data centers: Implications for providers, published July 2026*

Cumulative New Data Center Power Consumption Graph
- Bank of America-Watts to Token, May 2026

AI DC TAM CAGRs
- UB, Bank of America, Citi Bank, Mizuho and onsemi internal estimates

2026 estimates are based on consensus

Notes and Sources

Expanding the Core: Automotive and Industrial
Sudhir Gopalswamy, Group President, Analog & Mixed-Signal and Intelligent Sensing Groups

~0% SAAR 2019-26, 2026-2030
- Bloomberg Auto SAAR Factset 26E (0.39%)

Physical AI: $6B TAM in 2030
- **onsemi** estimates, Yole, Omdia projections for: Autonomous Mobile Robots, Drones, Humanoid

2026 estimates are based on consensus

Notes and Sources

Turning Technology Leadership into Durable Financial Performance
Thad Trent, Executive Vice President and CFO

What you are used to seeing (images)
- Maximize Market Research Pvt. Ltd
- Deloitte and Mordor Intelligence
- KBV Research
- Yole

Sustainable Ecosystem '22-'27 TAM CAGRs
- onsemi estimates
- LMC Automotive: Global Hybrid & Electric Vehicle Forecast - Quarter 4, 2022
- Omdia: Power IC Market Tracker, Sep'22

Sustainable Ecosystem Accelerating onsemi Content
- Based on total onsemi BOM opportunity

Markets that Matter
- onsemi estimates based on current market projections
- Semiconductor TAM excludes Memory

Winning Formula…and Execute
- >$17B: onsemi Form 10-Q filing for period ended March 31 2023

2026 estimates are based on consensus

Cautionary Information

No Offer or Solicitation

This communication is for informational purposes only and does not constitute, or form a part of, an offer to buy or sell or the solicitation of an offer to buy or sell any securities, or a solicitation of any vote or approval, nor shall there be any sale of securities in any jurisdiction in which such offer, solicitation or sale would be unlawful prior to registration or qualification under the securities laws of any such jurisdiction. No offer of securities shall be made except by means of a prospectus meeting the requirements of Section 10 of the Securities Act of 1933, as amended.

Important Additional Information about the Transaction and Where To Find It

The proposed transaction will be submitted to the stockholders of Synaptics for their consideration. In connection with the proposed transaction, on August 21, 2026, onsemi filed with the SEC a Registration Statement on Form S-4 that included a proxy statement of Synaptics and that also constituted a prospectus of onsemi. Each of Synaptics and onsemi will provide the proxy statement/prospectus to Synaptics stockholders. These materials are not yet finaland will be amended. Synaptics and onsemi also plan to file other documents with the SEC regarding the proposed transaction. This document is not a substitute for any prospectus, proxy statement or any other document which Synaptics or onsemi may file with the SEC in connection with the proposed transaction. INVESTORS AND SECURITY HOLDERS ARE URGED TO READ THE PROXY STATEMENT/PROSPECTUS AND ANY OTHER RELEVANT DOCUMENTS THAT WILL BE FILED WITH THE SEC CAREFULLY AND IN THEIR ENTIRETY WHEN THEY BECOME AVAILABLE BECAUSE THEY WILL CONTAIN IMPORTANT INFORMATION ABOUT THE PROPOSED TRANSACTION. You may obtain copies of all documents filed with the SEC regarding this transaction, free of charge, at the SEC's website (www.sec.gov). In addition, investors and stockholders will be able to obtain free copies of the proxy statement/prospectus and other documents filed with the SEC by the parties on Synaptics Investor Relations at https://investor.synaptics.com/ (for documents filed with the SEC by Synaptics) or onsemi Investor Relations at https://investor.onsemi.com/ (for documents filed with the SEC by onsemi).

Cautionary Information

Participants in the Solicitation

Synaptics, onsemi, and certain of their respective directors, executive officers and other members of management and employees, under SEC rules may be deemed to be participants in the solicitation of proxies from Synaptics stockholders in connection with the proposed transaction. Information regarding the persons who may, under the rules of the SEC, be deemed participants in the solicitation of Synaptics stockholders in connection with the proposed transaction, and a description of their direct and indirect interests, by security holdings or otherwise, will be set forth in the proxy statement/prospectus that will be provided to Synaptics stockholders. You can find more detailed information about Synaptics' executive officers and directors under the headings "Proposal 1 – Election of Directors," "Director Compensation," "Compensation Discussion and Analysis," "Named Executive Officer Compensation Tables," "CEO Pay Ratio Disclosure," "Pay Versus Performance Disclosure" and "Beneficial Ownership of Certain Stockholders" in its definitive proxy statement filed with the SEC on September 16, 2025. To the extent holdings of Synaptics common stock by the directors and executive officers of Synaptics have changed from the amounts of Synaptics common stock held by such persons as reflected therein, such changes have been or will be reflected on Statements of Change in Ownership on Form 4 filed with the SEC, which are available at https://www.sec.gov/edgar/browse/?CIK=817720&owner=exclude under the tab "Ownership Disclosures". You can find more detailed information about onsemi's executive officers and directors under the headings "The Board of Directors and Corporate Governance," "Compensation of Executive Officers" and "Stock Ownership" in its definitive proxy statement filed with the SEC on April 2, 2026. To the extent holdings of onsemi common stock by the directors and executive officers of onsemi have changed from the amounts of onsemi common stock held by such persons as reflected therein, such changes have been or will be reflected on Statements of Change in Ownership on Form 4 filed with the SEC, which are available at https://www.sec.gov/edgar/browse/?CIK=1097864&owner=exclude under the tab "Ownership Disclosures". Additional information about Synaptics' executive officers and directors and onsemi's executive officers and directors can be found in the above-referenced Registration Statement on Form S-4.